

## SUPER-LOW CURRENT CONSUMPTION 150 mA VOLTAGE REGULATOR WITH BUILT-IN HIGH-ACCURACY VOLTAGE DETECTOR AND RESET INPUT FUNCTION

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The S-1702 Series, developed based on CMOS technology, is a 150 mA output positive voltage regulator with a low dropout voltage, a high-accuracy output voltage, and low current consumption.

The S-1702 Series includes a voltage regulator with high-accuracy output voltage of  $\pm 1.0\%$  allowing to use a ceramic capacitor of 1.0  $\mu\text{F}$  or more, and a voltage detector that monitors the output/input voltage of the regulator. It also includes an overcurrent protection circuit that prevents the output current from exceeding the current capacitance of the output transistor and an output forcible discharge circuit for the regulator operation off.

Small SNT-6A package is available for the S-1702 Series. And an external small capacitor can be used, enabling high-density mounting. Its super-low current consumption makes the S-1702 Series ideal for mobile devices.

### ■ Features

#### Regulator block

- Output voltage: 1.5 V to 5.5 V, selectable in 0.05 V step
- Output voltage accuracy:  $\pm 1.0\%$
- Current consumption: Current consumption of regulator block: 9  $\mu\text{A}$  typ., 16  $\mu\text{A}$  max.
- Output current: Possible to output 150 mA ( $V_{\text{IN}} \geq V_{\text{OUT(S)}} + 1.0 \text{ V}$ )\*1
- Built-in overcurrent protection circuit: Limits overcurrent of output transistor.
- Built-in ON / OFF forcible discharge circuit: Ensures long battery life, discharges output load instantaneously.
- Ripple rejection: 70 dB typ. (f = 1.0 kHz)

#### Detector block

- Detection voltage: 1.3 V to 5.2 V, selectable in 0.05 V step
- Built-in high-accuracy voltage detection circuit:  $\pm 1.0\%$   
Monitoring output/input or monitoring external input by option (detector output)
- External reset input: Forcible assertion of detector output by external reset pin (RESX) input

#### Overall

- Correlation temperature gradient in the regulator and the detector blocks
- Current consumption: During operation\*2: 10  $\mu\text{A}$  typ., 18  $\mu\text{A}$  max.
- Operation temperature range:  $T_a = -40^\circ\text{C}$  to  $+85^\circ\text{C}$
- Lead-free (Sn 100%), halogen-free

\*1. Attention should be paid to the power dissipation of the package when the output current is large.

\*2. Excluding current flowing in pull-up and pull-down resistors connected to the ON / OFF or RESX pins

### ■ Applications

- Wireless power supply circuit block for cellular phone
- Power supply circuit block for health care product
- Power supply circuit block for various mobile device

### ■ Package

- SNT-6A

■ **Block Diagrams**

1. **S-1702 Series A type to H type**

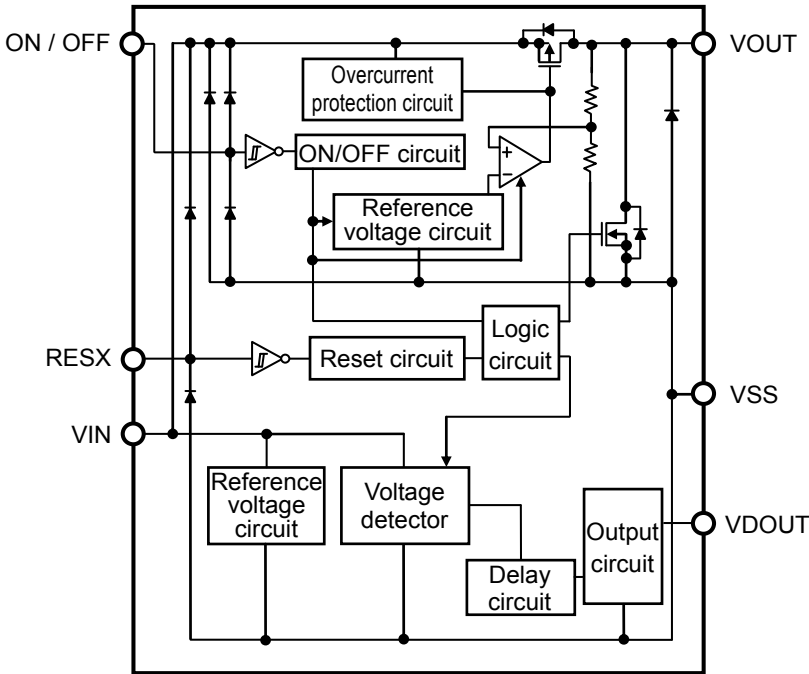


Figure 1

Product Type	Detector Monitor Voltage	Discharge Shunt Function by ON / OFF and RESX Pins	
		Control by ON / OFF Pin	Control by RESX Pin
A	V <sub>OUT</sub>	○	○
B	V <sub>OUT</sub>	○	×
C	V <sub>OUT</sub>	×	○
D	V <sub>OUT</sub>	×	×
E	V <sub>IN</sub>	○	○
F	V <sub>IN</sub>	○	×
G	V <sub>IN</sub>	×	○
H	V <sub>IN</sub>	×	×

2. **S-1702 Series J type and K type (external input detection type)**

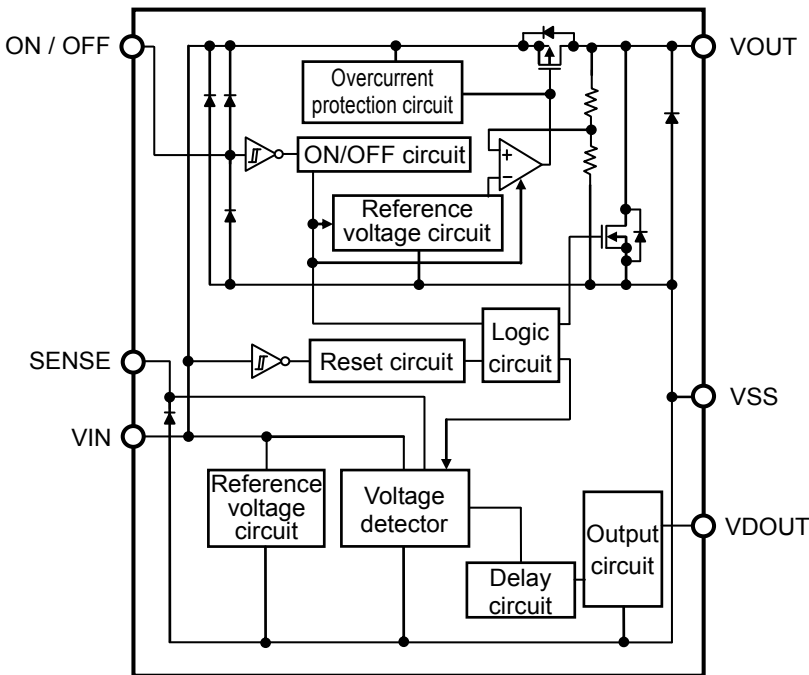
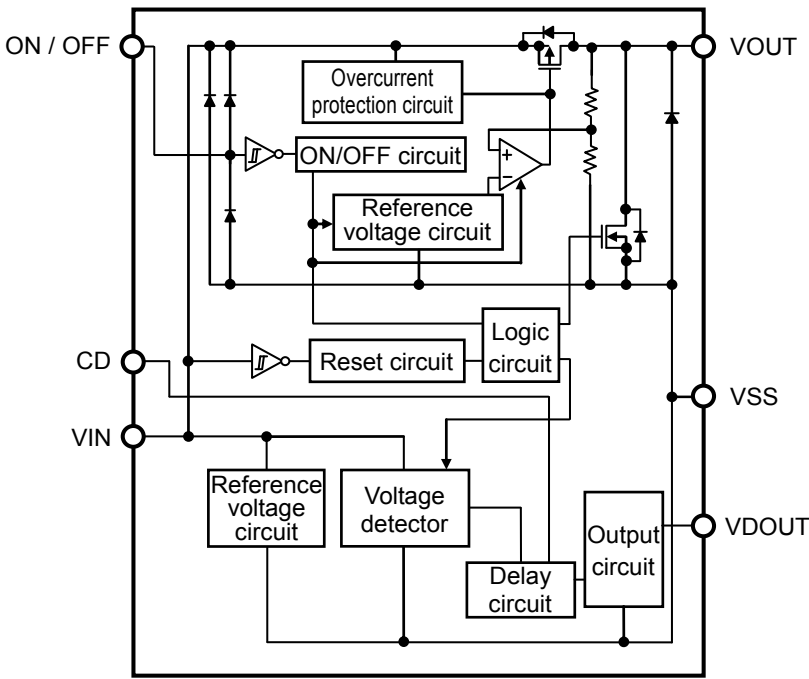


Figure 2

Product Type	Detector Monitor Voltage	Discharge Shunt Function by ON / OFF Pin
J	External input	○
K	External input	×

3. S-1702 Series L type to N type, P type (external delay type)

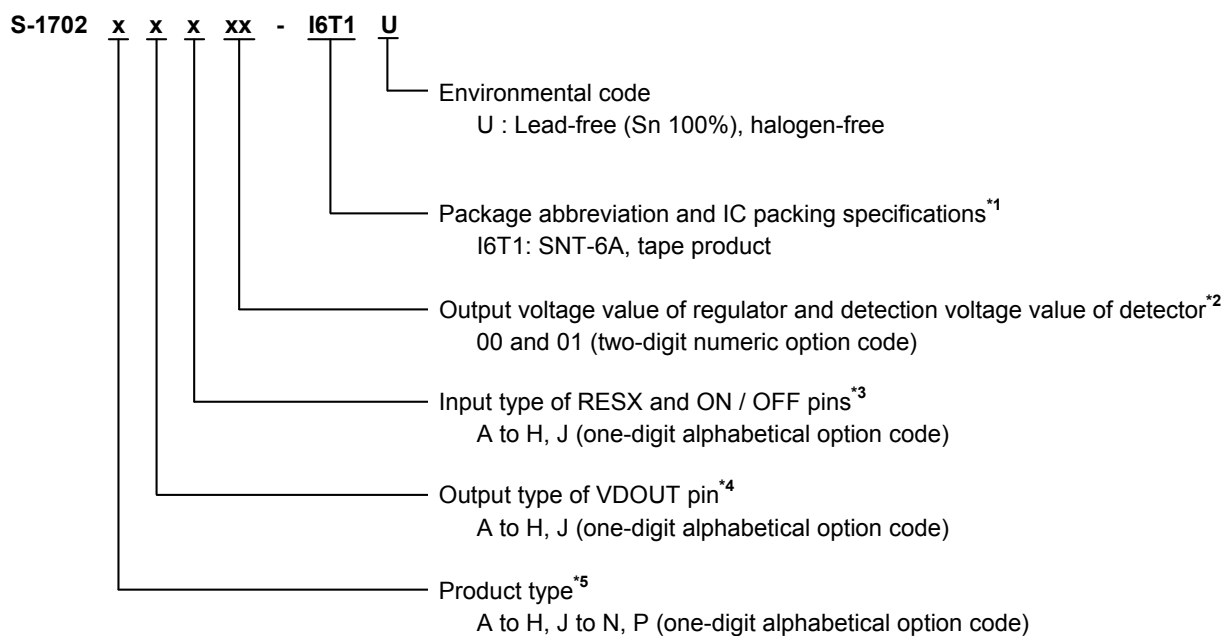


Product Type	Detector Monitor Voltage	Discharge Shunt Function by ON / OFF Pin
L	V <sub>OUT</sub>	○
M	V <sub>OUT</sub>	×
N	V <sub>IN</sub>	○
P	V <sub>IN</sub>	×

Figure 3

## ■ Product Name Structure

### 1. Product name



\*1. Refer to the tape drawing.

\*2. Refer to **Table 4** of “**2. Function list according to product type**”.

\*3. Refer to **Table 3** of “**2. Function list according to product type**”.

\*4. Refer to **Table 2** of “**2. Function list according to product type**”.

\*5. Refer to **Table 1** of “**2. Function list according to product type**”.

## 2. Function list according to product type

Table 1 Product Types

Option Code	ON / OFF Pin Application	RESX Pin Application	Delay Type	Detector Monitor Voltage	Discharge Shunt Function	
					Control by ON / OFF Pin	Control by RESX Pin
A	ON / OFF	RESX	Internal	$V_{OUT}$	○	○
B	ON / OFF	RESX	Internal	$V_{OUT}$	○	×
C	ON / OFF	RESX	Internal	$V_{OUT}$	×	○
D	ON / OFF	RESX	Internal	$V_{OUT}$	×	×
E	ON / OFF	RESX	Internal	$V_{IN}$	○	○
F	ON / OFF	RESX	Internal	$V_{IN}$	○	×
G	ON / OFF	RESX	Internal	$V_{IN}$	×	○
H	ON / OFF	RESX	Internal	$V_{IN}$	×	×
J	ON / OFF	SENSE	Internal	$V_{SENSE}$	○	–
K	ON / OFF	SENSE	Internal	$V_{SENSE}$	×	–
L	ON / OFF	CD	External	$V_{OUT}$	○	–
M	ON / OFF	CD	External	$V_{OUT}$	×	–
N	ON / OFF	CD	External	$V_{IN}$	○	–
P	ON / OFF	CD	External	$V_{IN}$	×	–

Table 2 Output Types of VDOUT Pin

Option Code	Output Type	Hysteresis
A	Nch open drain output	5.0%
B	CMOS output ( $V_{OUT}$ drive)	5.0%
C	CMOS output ( $V_{IN}$ drive)	5.0%
D	Nch open drain output	2.5%
E	CMOS output ( $V_{OUT}$ drive)	2.5%
F	CMOS output ( $V_{IN}$ drive)	2.5%
G	Nch open drain output	None
H	CMOS output ( $V_{OUT}$ drive)	None
J	CMOS output ( $V_{IN}$ drive)	None

**Table 3 Input Types of RESX and ON / OFF Pins**

Option Code	RESX Pin	ON / OFF Pin
A	No pull-up/pull-down resistor	No pull-up/pull-down resistor
B	No pull-up/pull-down resistor	Pull-up
C	No pull-up/pull-down resistor	Pull-down
D	Pull-up	No pull-up/pull-down resistor
E	Pull-up	Pull-up
F	Pull-up	Pull-down
G	Pull-down	No pull-up/pull-down resistor
H	Pull-down	Pull-up
J	Pull-down	Pull-down

**Table 4 Output Voltage Values of Regulator and Detection Voltage Values of Detector**

Option Code	Output Voltage	Detection Voltage
00	3.1 V $\pm$ 1.0%	2.75 V $\pm$ 1.0%
01	3.1 V $\pm$ 1.0%	2.60 V $\pm$ 1.0%

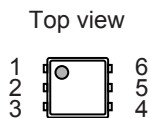
**Remark** Please contact our sales office for products with an output voltage or detection voltage other than those specified above.

### 3. Package

Package Name	Drawing Code			
	Package	Tape	Reel	Land
SNT-6A	PG006-A-P-SD	PG006-A-C-SD	PG006-A-R-SD	PG006-A-L-SD

■ **Pin Configuration**

1. **SNT-6A**



**Figure 4**

**Table 5**

Pin No.	Symbol	Description
1	VIN	Input voltage pin
2	ON / OFF	ON / OFF pin
3	RESX	External reset pin (S-1702Axx to Hxx)
	CD	External delay capacitor connection pin (S-1702Lxx to Nxx, Pxx)
	SENSE	Detector SENSE pin (S-1702Jxx, Kxx)
4	VSS	GND pin
5	VDOUT	Detector output voltage pin
6	VOUT	Regulator output voltage pin

■ **Absolute Maximum Ratings**

**Table 6**

(Ta = +25°C unless otherwise specified)

Item	Symbol	Absolute Maximum Rating	Unit
Input voltage	V <sub>IN</sub>	V <sub>SS</sub> - 0.3 to V <sub>SS</sub> + 7.0	V
	V <sub>ON / OFF</sub>	V <sub>SS</sub> - 0.3 to V <sub>IN</sub> + 0.3	V
	V <sub>RESX</sub>	V <sub>SS</sub> - 0.3 to V <sub>IN</sub> + 0.3	V
	V <sub>CD</sub>	V <sub>SS</sub> - 0.3 to V <sub>IN</sub> + 0.3	V
	V <sub>SENSE</sub>	V <sub>SS</sub> - 0.3 to V <sub>SS</sub> + 7.0	V
Regulator output voltage	V <sub>OUT</sub>	V <sub>SS</sub> - 0.3 to V <sub>IN</sub> + 0.3	V
Detector output voltage	Nch open drain output	V <sub>DDOUT</sub>	V <sub>SS</sub> - 0.3 to V <sub>SS</sub> + 7.0
	CMOS output		V <sub>SS</sub> - 0.3 to V <sub>IN</sub> + 0.3
Power dissipation	P <sub>D</sub>	400*1	mW
Operation ambient temperature	T <sub>opr</sub>	-40 to +85	°C
Storage temperature	T <sub>stg</sub>	-40 to +125	°C

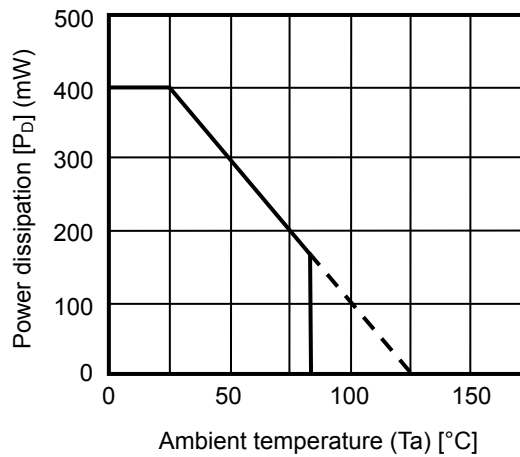
\*1. When mounted on board

[Mounted board]

(1) Board size : 114.3 mm × 76.2 mm × t1.6 mm

(2) Board name : JEDEC STANDARD51-7

**Caution** The absolute maximum ratings are rated values exceeding which the product could suffer physical damage. These values must therefore not be exceeded under any conditions.



**Figure 5 Power Dissipation of Package**



■ Electrical Characteristics

1. Common to series (S-1702Axx to Hxx, Jxx to Nxx, Pxx)

Table 7 (1 / 2)

Entire circuit

(Ta = +25°C unless otherwise specified)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Test Circuit
Current consumption during operation*1	I <sub>SS</sub>	V <sub>IN</sub> = V <sub>OUT(S)</sub> + 1.0 V	–	10	18	μA	2

Regulator block

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Test Circuit	
Output voltage*2	V <sub>OUT(E)</sub>	V <sub>IN</sub> = V <sub>OUT(S)</sub> + 1.0 V, I <sub>OUT</sub> = 30 mA	V <sub>OUT(S)</sub> × 0.99	V <sub>OUT(S)</sub>	V <sub>OUT(S)</sub> × 1.01	V	1	
Output current*3	I <sub>OUT</sub>	V <sub>IN</sub> > V <sub>OUT(S)</sub> + 1.0 V	150*8	–	–	mA	3	
Dropout voltage*4	V <sub>drop</sub>	I <sub>OUT</sub> = 100 mA	1.5 V < V <sub>OUT(S)</sub> ≤ 2.0 V	–	0.54	0.58	V	1
			2.0 V < V <sub>OUT(S)</sub> ≤ 2.5 V	–	0.23	0.35	V	1
			2.5 V < V <sub>OUT(S)</sub> ≤ 3.0 V	–	0.2	0.3	V	1
			3.0 V < V <sub>OUT(S)</sub> ≤ 3.3 V	–	0.15	0.23	V	1
			3.3 V < V <sub>OUT(S)</sub> ≤ 5.5 V	–	0.14	0.21	V	1
Line regulation	$\frac{\Delta V_{OUT1}}{\Delta V_{IN} \cdot V_{OUT}}$	V <sub>OUT(S)</sub> + 0.5 V < V <sub>IN</sub> < 6.5 V, I <sub>OUT</sub> = 30 mA	–	0.05	0.2	%/V	1	
Load regulation	ΔV <sub>OUT2</sub>	V <sub>IN</sub> = V <sub>OUT(S)</sub> + 1.0 V, 10 μA < I <sub>OUT</sub> < 100 mA	–	20	40	mV	1	
Output voltage temperature coefficient*5	$\frac{\Delta V_{OUT}}{\Delta T_a \cdot V_{OUT}}$	V <sub>IN</sub> = V <sub>OUT(S)</sub> + 1.0 V, I <sub>OUT</sub> = 30 mA, –40°C ≤ Ta ≤ +85°C*9	–	±100	±300	ppm/°C	1	
Current consumption during operation*1	I <sub>SS1</sub>	V <sub>IN</sub> = V <sub>OUT(S)</sub> + 1.0 V, RESX and ON / OFF pins enabled for operation, no load	–	9	16	μA	2	
Input voltage	V <sub>IN</sub>	–	2	–	6.5	V	–	
ON / OFF pin input voltage "H"	V <sub>SH1</sub>	V <sub>IN</sub> = V <sub>OUT(S)</sub> + 1.0 V, R <sub>L</sub> = 1.0 kΩ	1.2	–	–	V	4	
ON / OFF pin input voltage "L"	V <sub>SL1</sub>	V <sub>IN</sub> = V <sub>OUT(S)</sub> + 1.0 V, R <sub>L</sub> = 1.0 kΩ	–	–	0.3	V	4	
ON / OFF pin input current "H"	I <sub>SH1</sub>	V <sub>IN</sub> = 6.5 V, V <sub>ON / OFF</sub> = 6.5 V	S-1702xxA	–0.1	–	0.1	μA	4
			S-1702xxD	–0.1	–	0.1	μA	4
			S-1702xxG	–0.1	–	0.1	μA	4
ON / OFF pin input current "L"	I <sub>SL1</sub>	V <sub>IN</sub> = 6.5 V, V <sub>ON / OFF</sub> = 0 V	S-1702xxA	–0.1	–	0.1	μA	4
			S-1702xxD	–0.1	–	0.1	μA	4
			S-1702xxG	–0.1	–	0.1	μA	4
Ripple rejection	RR	V <sub>IN</sub> = V <sub>OUT(S)</sub> + 1.0 V, f = 1.0 kHz, ΔV <sub>rip</sub> = 0.5 V <sub>rms</sub> , I <sub>OUT</sub> = 30 mA	1.5 V ≤ V <sub>OUT(S)</sub> < 3.1 V	–	70	–	dB	5
			3.1 V ≤ V <sub>OUT(S)</sub> ≤ 5.5 V	–	65	–	dB	5
Short-circuit current	I <sub>SHORT</sub>	V <sub>IN</sub> = V <sub>OUT(S)</sub> + 1.0 V, ON / OFF pin enabled for operation, V <sub>OUT</sub> = 0 V	–	300	–	mA	5	

**Table 7 (2 / 2)**

**Detector block**

(Ta = +25°C unless otherwise specified)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Test Circuit	
Detection voltage*6	-V <sub>DET</sub>	-	-V <sub>DET(S)</sub> ×0.99	-V <sub>DET(S)</sub>	-V <sub>DET(S)</sub> ×1.01	V	6	
Hysteresis width	V <sub>HYS</sub>	S-1702xAx, S-1702xBx, S-1702xCx	-V <sub>DET</sub> ×0.035	-V <sub>DET</sub> ×0.05	-V <sub>DET</sub> ×0.065	V	6	
		S-1702xDx, S-1702Ex, S-1702xFx	-V <sub>DET</sub> ×0.01	-V <sub>DET</sub> ×0.025	-V <sub>DET</sub> ×0.04	V	6	
		S-1702xGx, S-1702xHx, S-1702xJx	-	0	-V <sub>DET</sub> ×0.015	V	6	
Current consumption during operation*1	I <sub>SS2</sub>	1.3 V ≤ -V <sub>DET(S)</sub> < 2.3 V	V <sub>IN</sub> = -V <sub>DET(S)</sub> + 1.5 V	-	2.4	4.0	μA	2
			V <sub>IN</sub> = 5.5 V	-	2.6	4.5	μA	2
		2.3 V ≤ -V <sub>DET(S)</sub> < 5.2 V	V <sub>IN</sub> = -V <sub>DET(S)</sub> + 1.5 V	-	2.2	3.5	μA	2
			V <sub>IN</sub> = 5.5 V	-	2.3	4.0	μA	2
Input voltage	V <sub>IN</sub>	-	0.8	-	6.5	V	-	
Detection voltage temperature coefficient*7	$\frac{\Delta -V_{DET}}{\Delta Ta \cdot -V_{DET}}$	Ta = -40°C to +85°C*9	-	±100	±400	ppm/ °C	6	

- \*1. Excluding current flowing in pull-up and pull-down resistors connected to the ON / OFF or RESX pins
- \*2. V<sub>OUT(S)</sub>: Set output voltage  
 V<sub>OUT(E)</sub>: Actual output voltage  
 Output voltage when fixing I<sub>OUT</sub> (= 30 mA) and inputting V<sub>OUT(S)</sub> + 1.0 V
- \*3. The output current at which the output voltage becomes 95% of V<sub>OUT(E)</sub> after gradually increasing the output current.
- \*4. V<sub>drop</sub> = V<sub>IN1</sub> - (V<sub>OUT3</sub> × 0.98)  
 V<sub>OUT3</sub> is the output voltage when V<sub>IN</sub> = V<sub>OUT(S)</sub> + 1.0 V and I<sub>OUT</sub> = 100 mA.  
 V<sub>IN1</sub> is the input voltage at which the output voltage becomes 98% of V<sub>OUT3</sub> after gradually decreasing the input voltage.
- \*5. A change in the temperature of the regulator output voltage [mV/°C] is calculated using the following equation.  

$$\frac{\Delta V_{OUT}}{\Delta Ta} \text{ [mV/°C]}^{*1} = V_{OUT(S)} \text{ [V]}^{*2} \times \frac{\Delta V_{OUT}}{\Delta Ta \cdot V_{OUT}} \text{ [ppm/°C]}^{*3} \div 1000$$
  - \*1. Change in temperature of output voltage
  - \*2. Set output voltage
  - \*3. Output voltage temperature coefficient
- \*6. -V<sub>DET(S)</sub> : Set detection voltage  
 -V<sub>DET</sub> : Actual detection voltage
- \*7. A change in the temperature of the detector detection voltage [mV/°C] is calculated using the following equation.  

$$\frac{\Delta -V_{DET}}{\Delta Ta} \text{ [mV/°C]}^{*1} = -V_{DET(S)} \text{ (Typ.) [V]}^{*2} \times \frac{\Delta -V_{DET}}{\Delta Ta \cdot -V_{DET}} \text{ [ppm/°C]}^{*3} \div 1000$$
  - \*1. Change in temperature of detection voltage
  - \*2. Set detection voltage
  - \*3. Detection voltage temperature coefficient
- \*8. The output current can be at least this value.  
 Due to restrictions on the package power dissipation, this value may not be satisfied. Attention should be paid to the power dissipation of the package when the output current is large. This specification is guaranteed by design.
- \*9. Since products are not screened at high and low temperatures, the specification for this temperature range is guaranteed by design, not tested in production.

**2. Discharge shunt circuit (discharge shunt function) (S-1702Axx, Bxx, Cxx, Exx, Fxx, Gxx, Jxx, Lxx, Nxx)**

**Table 8**

(Ta = +25°C unless otherwise specified)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Test Circuit
"L" output, Nch on resistor	R <sub>LOW</sub>	V <sub>DS</sub> = 0.5 V, V <sub>GS</sub> = 6.5 V	–	100	–	Ω	3

**3. Detector output circuit (VDOUT pin)**

**Table 9**

**Nch open drain output (S-1702xAx, xDx, xGx)**

(Ta = +25°C unless otherwise specified)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Test Circuit
Output current	I <sub>DOUT1</sub>	Output transistor: Nch, V <sub>DS</sub> = 0.5 V, V <sub>DD</sub> = 1.2 V	1.36	2.55	–	mA	7
Leakage current	I <sub>LEAK</sub>	Output transistor: Nch, V <sub>DS</sub> = 5.5 V, V <sub>DD</sub> = 5.5 V	–	–	100	nA	7

**CMOS output (S-1702xBx, xCx, xEx, xFx, xHx, xJx)**

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Test Circuit
Output current	I <sub>DOUT2</sub>	Output transistor: Nch, V <sub>DS</sub> = 0.5 V, V <sub>IN</sub> = 1.2 V	1.36	2.55	–	mA	7
	I <sub>DOUT3</sub>	Output transistor: Pch, V <sub>DS</sub> = 0.5 V, V <sub>IN</sub> = 5.5 V	1.71	2.76	–	mA	8

**4. RESX pin (S-1702Axx, Bxx, Cxx, Dxx, Exx, Fxx, Gxx, Hxx)**

**Table 10**

(Ta = +25°C unless otherwise specified)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Test Circuit	
RESX pin input voltage "H" <sup>*1</sup>	V <sub>SH2</sub>	V <sub>IN</sub> = V <sub>OUT(S)</sub> + 1.0 V, R <sub>L</sub> = 1.0 kΩ	1.2	–	–	V	4	
RESX pin input voltage "L"	V <sub>SL2</sub>	V <sub>IN</sub> = V <sub>OUT(S)</sub> + 1.0 V, R <sub>L</sub> = 1.0 kΩ	–	–	0.3	V	4	
RESX pin input current "H"	I <sub>SH2</sub>	V <sub>IN</sub> = 6.5 V, V <sub>RESX</sub> = 6.5 V	S-1702xxA	–0.1	–	0.1	μA	4
			S-1702xxB	–0.1	–	0.1	μA	4
			S-1702xxC	–0.1	–	0.1	μA	4
RESX pin input current "L"	I <sub>SL2</sub>	V <sub>IN</sub> = 6.5 V, V <sub>RESX</sub> = 0 V	S-1702xxA	–0.1	–	0.1	μA	4
			S-1702xxB	–0.1	–	0.1	μA	4
			S-1702xxC	–0.1	–	0.1	μA	4

\*1. V<sub>OUT(S)</sub>: set output voltage value

**5. Pull-up / pull-down resistor value of ON / OFF pin and RESX pin (S-1702xxB, xxC, xxD, xxE, xxF, xxG, xxH, xxJ)**

**Table 11**

(Ta = +25°C unless otherwise specified)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Test Circuit
Pull-up / pull-down resistor	R <sub>PULL</sub>	–	–	2.0	–	MΩ	4

**6. Response time**

**Table 12**

**Internal delay type (S-1702Axx, Bxx, Cxx, Dxx, Exx, Fxx, Gxx, Hxx, Jxx, Kxx)** (Ta = +25°C unless otherwise specified)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Test Circuit
Response time	T <sub>PLH1</sub>	–	–	–	90	μs	6

**External delay type (S-1702Lxx, Mxx, Nxx, Pxx)**

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Test Circuit
Response time	T <sub>PLH2</sub>	C <sub>D</sub> = 4.7 nF	–	30	–	ms	9

■ Test Circuits

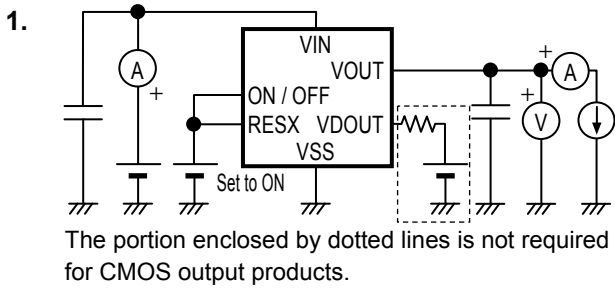


Figure 6

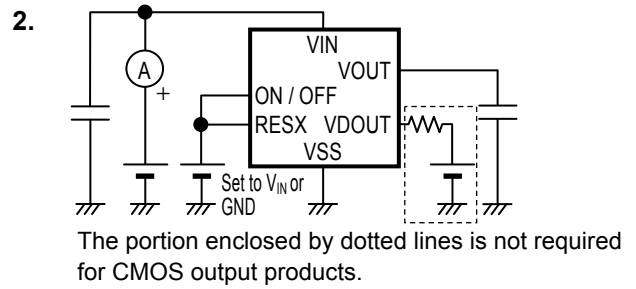


Figure 7

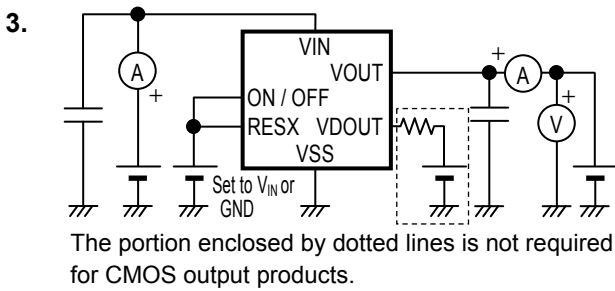


Figure 8

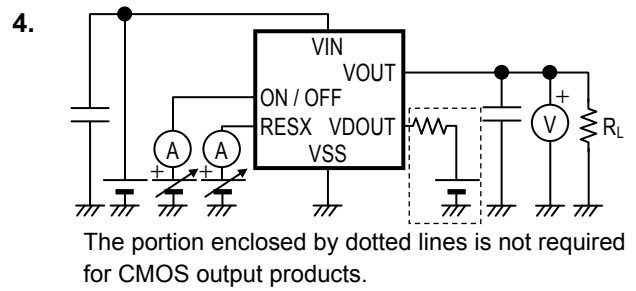


Figure 9

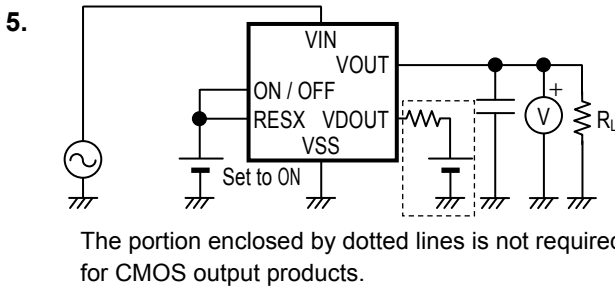


Figure 10

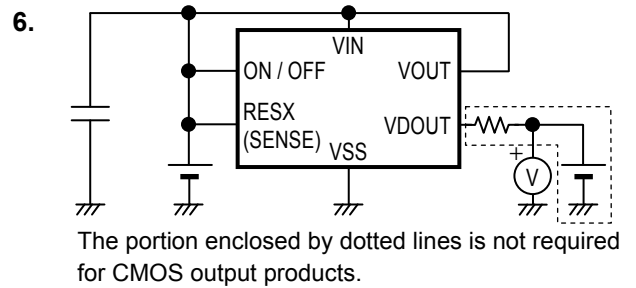


Figure 11

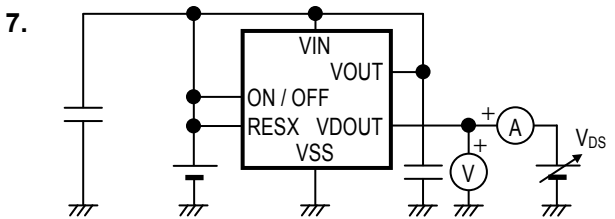


Figure 12

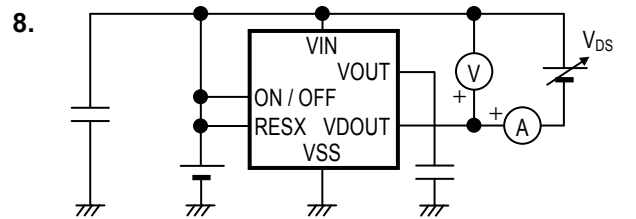


Figure 13

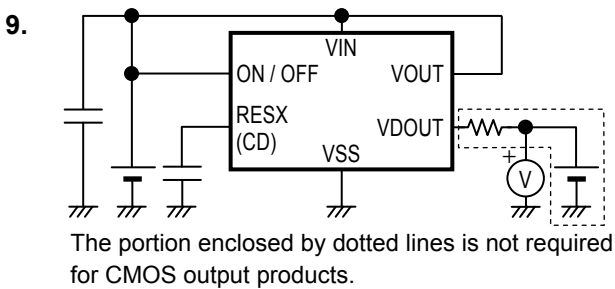
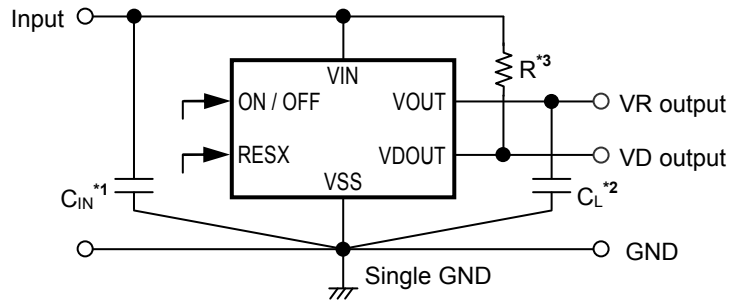


Figure 14

■ **Standard Circuits**

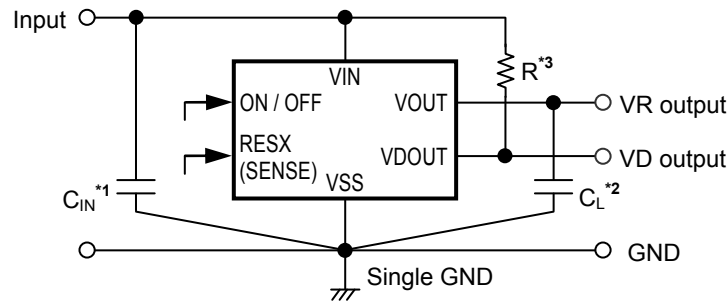
1. **S-1702Axx, Bxx, Cxx, Dxx, Exx, Fxx, Gxx, Hxx**



- \*1.  $C_{IN}$  is a capacitor for stabilizing the input.
- \*2. A ceramic capacitor of 1.0  $\mu\text{F}$  or more can be used for  $C_L$ .
- \*3. R is not required for a CMOS output product.

**Figure 15**

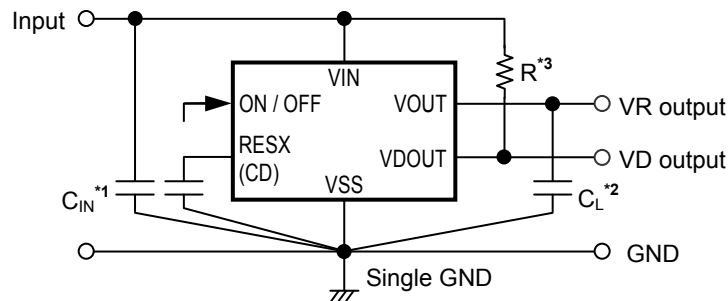
2. **S-1702Jxx, Kxx**



- \*1.  $C_{IN}$  is a capacitor for stabilizing the input.
- \*2. A ceramic capacitor of 1.0  $\mu\text{F}$  or more can be used for  $C_L$ .
- \*3. R is not required for a CMOS output product.

**Figure 16**

3. **S-1702Lxx, Mxx, Nxx, Pxx**



- \*1.  $C_{IN}$  is a capacitor for stabilizing the input.
- \*2. A ceramic capacitor of 1.0  $\mu\text{F}$  or more can be used for  $C_L$ .
- \*3. R is not required for a CMOS output product.

**Figure 17**

**Caution** The above connection diagrams and constants will not guarantee successful operation. Perform thorough evaluation using the actual application to set the constants.

## ■ Condition of Application

Input capacitor ( $C_{IN}$ ): 1.0  $\mu$ F or more

Output capacitor ( $C_L$ ): 1.0  $\mu$ F or more

ESR of output capacitor: 10  $\Omega$  or less

**Caution** Generally a series regulator may cause oscillation, depending on the selection of external parts. Confirm that no oscillation occurs in the application for which the above capacitors are used.

## ■ Selection of VIN Input and VOUT Output Capacitors ( $C_{IN}$ , $C_L$ )

The S-1702 Series requires an output capacitor ( $C_L$ ) between the VOUT and VSS pins for phase compensation. A ceramic capacitor with a capacitance of 1.0  $\mu$ F or more provides a stable operation in all temperature ranges. When using an OS capacitor, a tantalum capacitor, or an aluminum electrolytic capacitor, a capacitance must be 1.0  $\mu$ F or more, and the ESR must be 10  $\Omega$  or less.

The output overshoot and undershoot values, which are transient response characteristics, vary depending on the output capacitor value. The required capacitance value for the input capacitor differs depending on the application.

The recommended application values are  $C_{IN} \geq 1.0 \mu\text{F}$  and  $C_L \geq 1.0 \mu\text{F}$ ; however, perform thorough evaluation using the actual device, including evaluation of temperature characteristics.

## ■ Explanation of Terms

### 1. Regulator block

#### 1.1 Low dropout voltage regulator

This voltage regulator has the low dropout voltage due to its built-in low on-resistance transistor.

#### 1.2 Low ESR

A capacitor whose ESR (Equivalent Series Resistance) is low. The S-1702 Series enables use of a low ESR capacitor, such as a ceramic capacitor, for the output-side capacitor ( $C_L$ ). A capacitor whose ESR is 10  $\Omega$  or less can be used.

#### 1.3 Output voltage ( $V_{OUT}$ )

The accuracy of the output voltage is ensured at  $\pm 1.0\%$  under the specified conditions of fixed input voltage\*1, fixed output current, and fixed temperature.

\*1. Differs depending on the product.

**Caution** If the above conditions change, the output voltage value may vary and exceed the accuracy range of the output voltage. Refer to “■ Electrical Characteristics” and “■ Characteristics (Typical Data)” for details.

#### 1.4 Line regulation $\left( \frac{\Delta V_{OUT1}}{\Delta V_{IN} \bullet V_{OUT}} \right)$

Indicates the dependency of the output voltage on the input voltage. That is, the values show how much the output voltage changes due to a change in the input voltage with the output current remaining unchanged.

#### 1.5 Load regulation ( $\Delta V_{OUT2}$ )

Indicates the dependency of the output voltage on the output current. That is, the values show how much the output voltage changes due to a change in the output current with the input voltage remaining unchanged.

#### 1.6 Dropout voltage ( $V_{drop}$ )

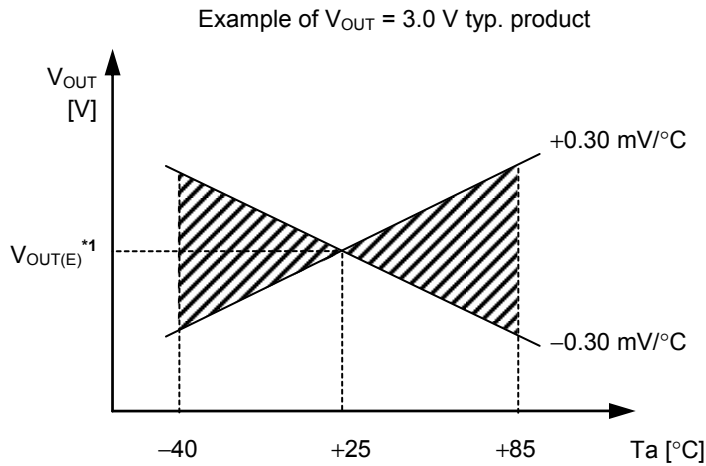
Indicates the difference between input voltage ( $V_{IN1}$ ) and the output voltage when; decreasing input voltage ( $V_{IN}$ ) gradually until the output voltage has dropped out to the value of 98% of output voltage ( $V_{OUT3}$ ), which is at  $V_{IN} = V_{OUT(S)} + 1.0$  V.

$$V_{drop} = V_{IN1} - (V_{OUT3} \times 0.98)$$



**1.7 Output voltage temperature coefficient**  $\left( \frac{\Delta V_{OUT}}{\Delta T_a \bullet V_{OUT}} \right)$

The shaded area in **Figure 18** is the range where  $V_{OUT}$  varies in the operation temperature range when the output voltage temperature coefficient is  $\pm 100$  ppm/ $^{\circ}\text{C}$  (Refer to \*5 of **Table 7** for how to calculate the temperature change of the output voltage [mV/ $^{\circ}\text{C}$ ]).



\*1.  $V_{OUT(E)*1}$  is the value of the output voltage measured at  $T_a = +25^{\circ}\text{C}$ .

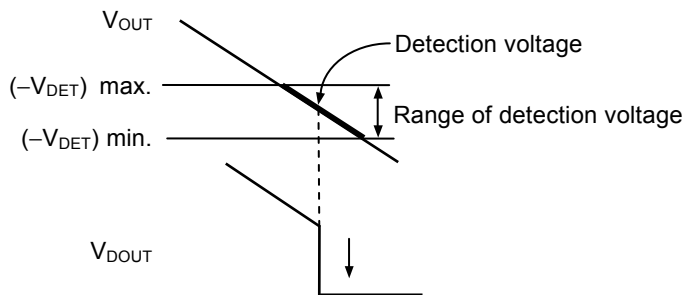
**Figure 18**

**2. Detector block**

**2.1 Detection voltage ( $-V_{DET}$ )**

The detection voltage ( $-V_{DET}$ ) is a voltage when the detector output voltage ( $V_{DOUT}$ ) switches to low. This detection voltage varies slightly depending on products even having the same specification. The range between the minimum ( $-V_{DET}$ ) value and the maximum ( $-V_{DET}$ ) value due to variation is called the range of detection voltage (refer to **Figure 19**).

e.g. In a product with  $-V_{DET} = 3.0$  V, the detection voltage is a value in the range of  $2.97$  V  $\leq (-V_{DET}) \leq 3.03$  V.  
 This means that some products have 2.97 V for  $-V_{DET}$  and some have 3.03 V.



**Remark** This is the case when the regulator output voltage ( $V_{OUT}$ ) is monitored by the detector.

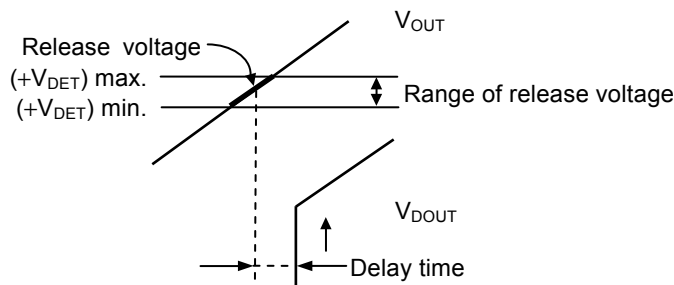
**Figure 19 Detection Voltage ( $-V_{DET}$ )**

**2.2 Release voltage ( $+V_{DET}$ )**

The release voltage ( $+V_{DET}$ ) is a voltage when the detector output voltage ( $V_{DOUT}$ ) switches to high. This release voltage varies slightly depending on products even having the same specification. The range between the minimum ( $+V_{DET}$ ) value and the maximum ( $+V_{DET}$ ) value due to variation is called the range of release voltage (refer to **Figure 20**).

e.g. In a product with  $-V_{DET} = 3.0$  V and hysteresis width of 5%, the release voltage is a value in the range of  $3.074$  V  $\leq (+V_{DET}) \leq 3.227$  V.

This means that some products have 3.074 V for  $+V_{DET}$  and some have 3.227 V.



**Remark** This is the case when the regulator output voltage ( $V_{OUT}$ ) is monitored by the detector.

**Figure 20 Release Voltage ( $+V_{DET}$ )**

**2.3 Hysteresis width ( $V_{HYS}$ )**

The hysteresis width is the difference between the detection voltage and the release voltage. Setting the hysteresis width prevents malfunction caused by noise on the input voltage. The hysteresis width is internally fixed and varies depending on the product type for details, refer to “Table 2 Output Types of VDOUT Pin”.

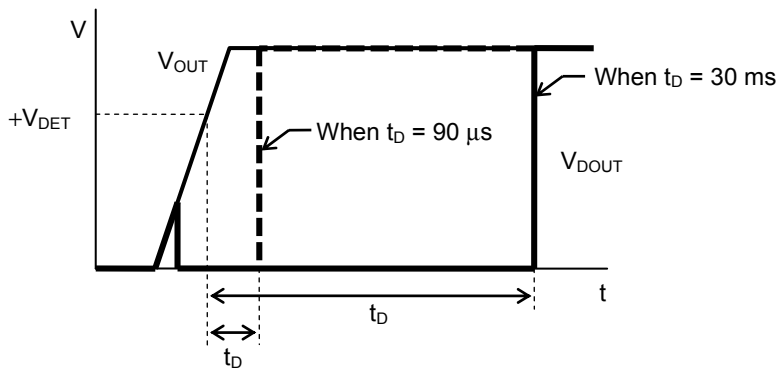
**2.4 Delay time ( $t_D$ )**

The delay time ( $t_D$ ) is a period from the input voltage flowing to the detector block has exceeded the release voltage ( $+V_{DET}$ ), until the detector output voltage ( $V_{DOUT}$ ) inverts.

The internal delay type products (S-1702Axx, Bxx, Cxx, Dxx, Exx, Fxx, Gxx, Hxx, Jxx, Kxx) have delay time which is internally fixed.

In external delay type products (S-1702Lxx, Mxx, Nxx, Pxx), the delay time ( $t_D$ ) can be changed by controlling the capacitance value of the capacitor ( $C_D$ ) connected between the CD (RESX) and VSS pins.

For how to set the delay time ( $t_D$ ), refer to “3.2 Delay circuit” in “3. Detector block” in “■ Operation”.



**Remark** This is the case when the regulator output voltage ( $V_{OUT}$ ) is monitored by the detector.

**Figure 21**

**2.5 Through-type current**

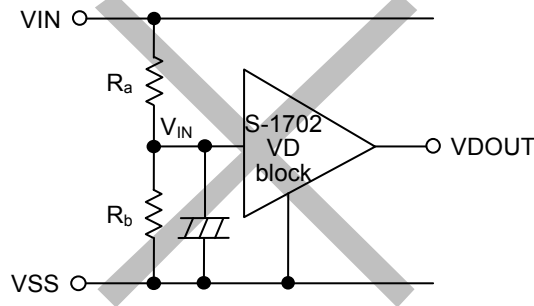
This is the current that flows instantaneously when the voltage detector detects and releases a voltage.

A large through-type current flows in CMOS output products (S-1702xBx, xCx, xEx, xFx, xHx, xJx).

A small through-type current flows in Nch open drain products (S-1702xAx, xDx, xGx).

**2.6 Oscillation**

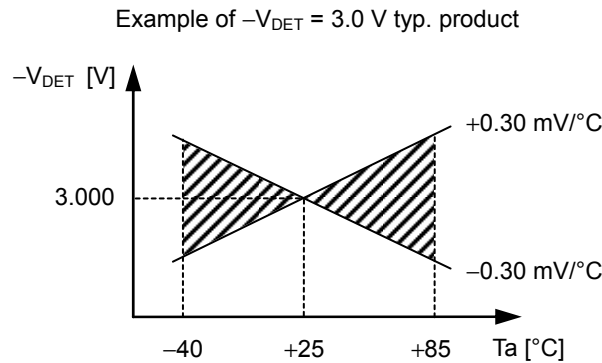
In applications where a resistor is connected to the input side (**Figure 22**), the through-type current which is generated when the detector output voltage ( $V_{DOUT}$ ) goes from low to high (release) causes a voltage drop equal to Through-type current  $\times$  Input resistance across the resistor. When the input voltage drops below the detection voltage as a result, the detector output voltage ( $V_{DOUT}$ ) goes from high to low. In this state, the through-type current stops, its resultant voltage drop disappears, and the detector output voltage ( $V_{DOUT}$ ) goes from low to high. The through-type current is then generated again, a voltage drop appears, and repeating the process finally induces oscillation.



**Figure 22 Example of Bad Implementation of Detection Voltage Changer**

**2.7 Detection voltage temperature characteristics**

The shaded area in **Figure 23** is the range where  $-V_{DET}$  varies within the operation temperature range when the detection voltage temperature coefficient is  $\pm 100$  ppm/ $^{\circ}C$  (Refer to \*7 of **Table 7** for how to calculate the temperature change of the detection voltage [mV/ $^{\circ}C$ ]).



**Figure 23**

**2.8 Release voltage temperature characteristics**

The temperature change  $\frac{\Delta + V_{DET}}{\Delta Ta}$  of the release voltage is calculated by the temperature change  $\frac{\Delta - V_{DET}}{\Delta Ta}$  of the detection voltage as follows:

$$\frac{\Delta + V_{DET}}{\Delta Ta} = \frac{+V_{DET}}{-V_{DET}} \times \frac{\Delta - V_{DET}}{\Delta Ta}$$

The temperature changes of the release voltage and the detection voltage consequently have the same sign.

**2.9 Hysteresis voltage temperature characteristics**

The temperature change of the hysteresis voltage is expressed as  $\frac{\Delta + V_{DET}}{\Delta Ta} - \frac{\Delta - V_{DET}}{\Delta Ta}$  and is calculated as follows:

$$\frac{\Delta + V_{DET}}{\Delta Ta} - \frac{\Delta - V_{DET}}{\Delta Ta} = \frac{V_{HYS}}{-V_{DET}} \times \frac{\Delta - V_{DET}}{\Delta Ta}$$

## ■ Operation

### 1. Control of S-1702 Series by using ON / OFF and RESX pins

#### 1.1 Starting and stopping regulator block

The regulator block can be started and stopped according to the combination of the ON / OFF and RESX pins.

The regulator block switches off the output transistor between the VIN pin and VOUT pin and reduces current consumption significantly.

The detector block is operating during this period, so only the amount of current consumed by the detector block flows in the S-1702 Series.

#### 1.2 Regulator output ( $V_{OUT}$ ) control: discharge shunt function \*1

The regulator output ( $V_{OUT}$ ) can be controlled by combining the ON / OFF and RESX pins.

In the product types having a discharge shunt circuit\*1 (Axx, Bxx, Cxx, Exx, Fxx, Gxx, Jxx, Lxx, Nxx), this circuit forcibly sets the regulator output ( $V_{OUT}$ ) the  $V_{SS}$  level\*1.

In the product types that do not have a discharge shunt circuit\*1 (Dxx, Hxx, Kxx, Mxx, Pxx), the regulator output ( $V_{OUT}$ ) is set at the  $V_{SS}$  level by a division resistor of several  $M\Omega$  between the VOUT pin and VSS pin.

\*1. For details of a discharge shunt circuit, refer to “2. 2. 2 Discharge shunt function” in “2. Regulator Block”.

#### 1.3 Detector output voltage ( $V_{DOUT}$ ) control: forcible assertion function

The detector output voltage ( $V_{DOUT}$ ) is forcibly asserted to the  $V_{SS}$  level by combining the ON / OFF and RESX pins.

When the forcible assertion function is not being used, the result of detection by the detector (release status: “H”, detection status: “L”) is output from the VDOUT pin.

**1.4 Operation of each function according to ON / OFF and RESX pins**

The following shows the operation of each function according to the combination of the ON / OFF and RESX pin.

**Table 13**

**S-1702Axx, Exx**

ON / OFF Pin	RESX Pin	Regulator Block	Regulator Output (V <sub>OUT</sub> )	Detector Output (V <sub>DOUT</sub> )
"L"	"L"	Stops	Forcibly discharged	V <sub>SS</sub> potential
"L"	"H"	Stops	Forcibly discharged	V <sub>SS</sub> potential
"H"	"L"	Stops	Forcibly discharged	V <sub>SS</sub> potential
"H"	"H"	Starts	Set value	"H" or "L"

**S-1702Bxx, Fxx**

ON / OFF Pin	RESX Pin	Regulator Block	Regulator Output (V <sub>OUT</sub> )	Detector Output (V <sub>DOUT</sub> )
"L"	"L"	Stops	Forcibly discharged	V <sub>SS</sub> potential
"L"	"H"	Stops	Forcibly discharged	V <sub>SS</sub> potential
"H"	"L"	Starts	Set value	V <sub>SS</sub> potential
"H"	"H"	Starts	Set value	"H" or "L"

**S-1702Cxx, Gxx**

ON / OFF Pin	RESX Pin	Regulator Block	Regulator Output (V <sub>OUT</sub> )	Detector Output (V <sub>DOUT</sub> )
"L"	"L"	Stops	Forcibly discharged	V <sub>SS</sub> potential
"L"	"H"	Stops	Not forcibly discharged	"H" or "L"
"H"	"L"	Stops	Forcibly discharged	V <sub>SS</sub> potential
"H"	"H"	Starts	Set value	"H" or "L"

**S-1702Dxx, Hxx**

ON / OFF Pin	RESX Pin	Regulator Block	Regulator Output (V <sub>OUT</sub> )	Detector Output (V <sub>DOUT</sub> )
"L"	"L"	Stops	Not forcibly discharged	V <sub>SS</sub> potential
"L"	"H"	Stops	Not forcibly discharged	"H" or "L"
"H"	"L"	Starts	Set value	V <sub>SS</sub> potential
"H"	"H"	Starts	Set value	"H" or "L"

**S-1702Jxx, Lxx, Nxx**

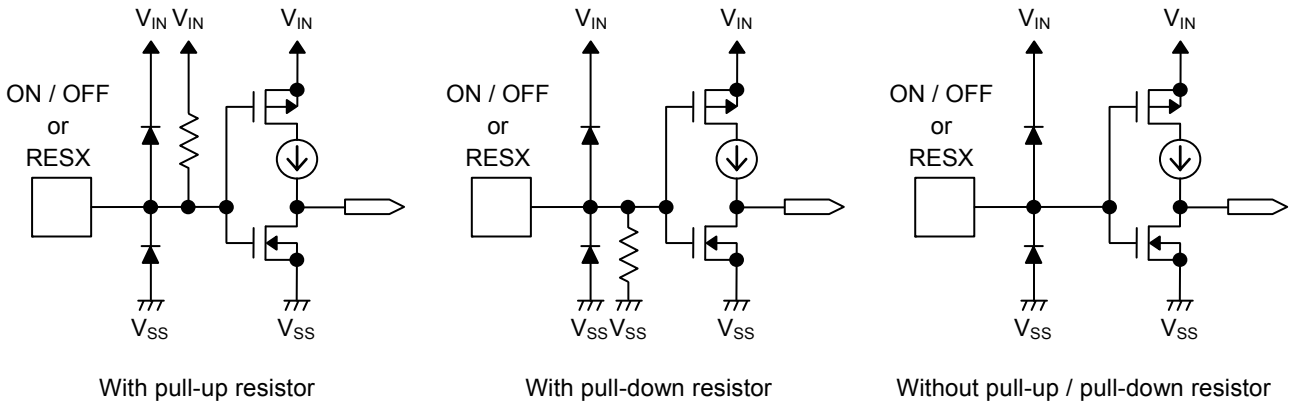
ON / OFF Pin	Regulator Block	Regulator Output (V <sub>OUT</sub> )	Detector Output (V <sub>DOUT</sub> )
"L"	Stops	Forcibly discharged	V <sub>SS</sub> potential
"H"	Starts	Set value	"H" or "L"

**S-1702Kxx, Mxx, Pxx**

ON / OFF Pin	Regulator Block	Regulator Output (V <sub>OUT</sub> )	Detector Output (V <sub>DOUT</sub> )
"L"	Stops	Not forcibly discharged	"H" or "L"
"H"	Starts	Set value	"H" or "L"

**1.5 Equivalent circuits of ON / OFF and RESX pins**

The ON / OFF and RESX pins are internally fixed to any one of three states; pulled-up (via a pull-up resistor), pulled-down (via a pull-down resistor), or neither pulled-up nor pulled-down (no down pull-up / pull-down resistor). For details, refer to “Table 3 Input Types of RESX and ON / OFF Pins”. The equivalent circuits are shown below.



**Figure 24 Equivalent Circuits of ON / OFF and RESX Pins**

**Caution** In product without pull-up / pull-down resistor, do not use the ON / OFF and RESX pins in a floating status.  
 Note that applying voltage of 0.3 V to 1.2 V may increase current consumption.

## 2. Regulator block

### 2.1 Basic operation

Figure 25 shows a block diagram of the regulator block.

The error amplifier compares the reference voltage ( $V_{ref}$ ) with feedback voltage ( $V_{fb}$ ), which is the output voltage resistance-divided by feedback resistors ( $R_s$  and  $R_f$ ). It supplies the gate voltage necessary to maintain the constant output voltage which is not influenced by the input voltage and temperature change, to the output transistor.

The regulator output voltage ( $V_{OUT}$ ) of the S-1702 Series can be selected from a value between 1.5 V and 5.5 V.

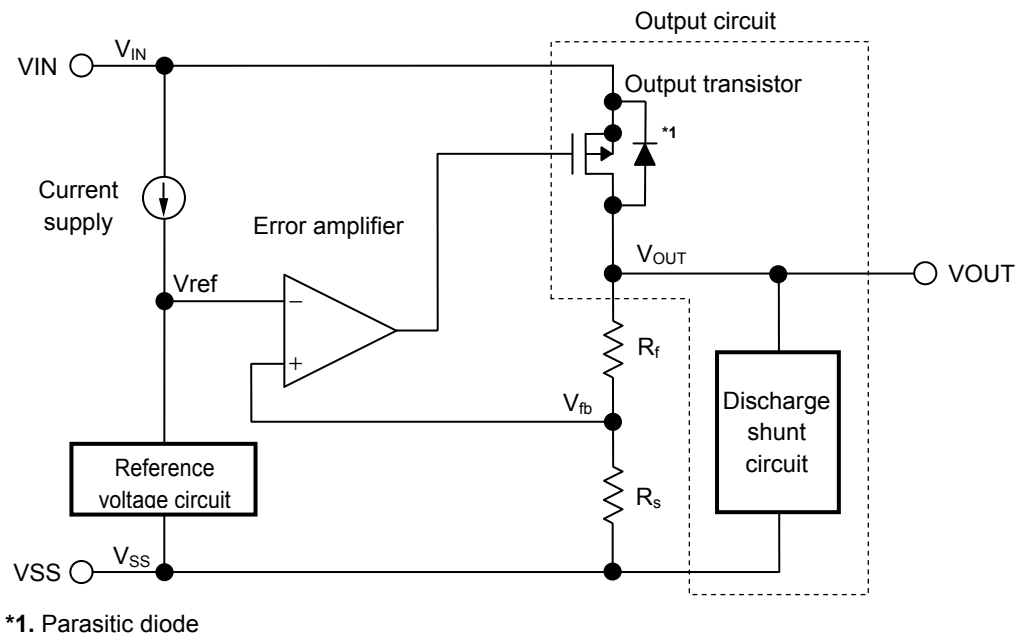
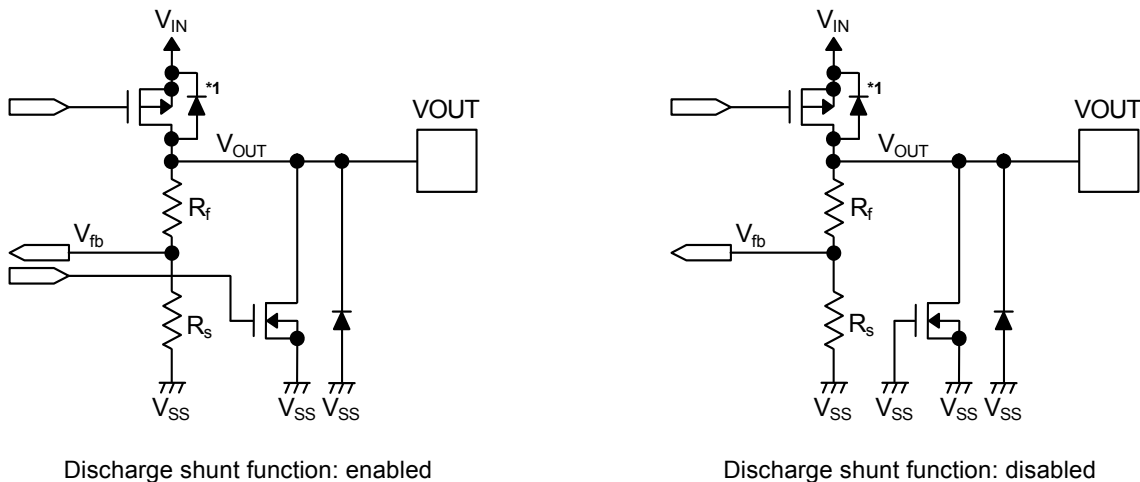


Figure 25

### 2.2 Output circuit

The output circuit of the regulator block consists of an output transistor and a discharge shunt circuit.

The discharge shunt function is enabled or disabled for the VOUT pin. Refer to “Table 1 Product Types” for details. The equivalent circuits are shown below.



\*1. Parasitic diode

Figure 26 Equivalent Circuits of VOUT Pin



**2. 2. 1 Output transistor**

The S-1702 Series regulator block uses a low on-resistance Pch MOS FET transistor as the output transistor.

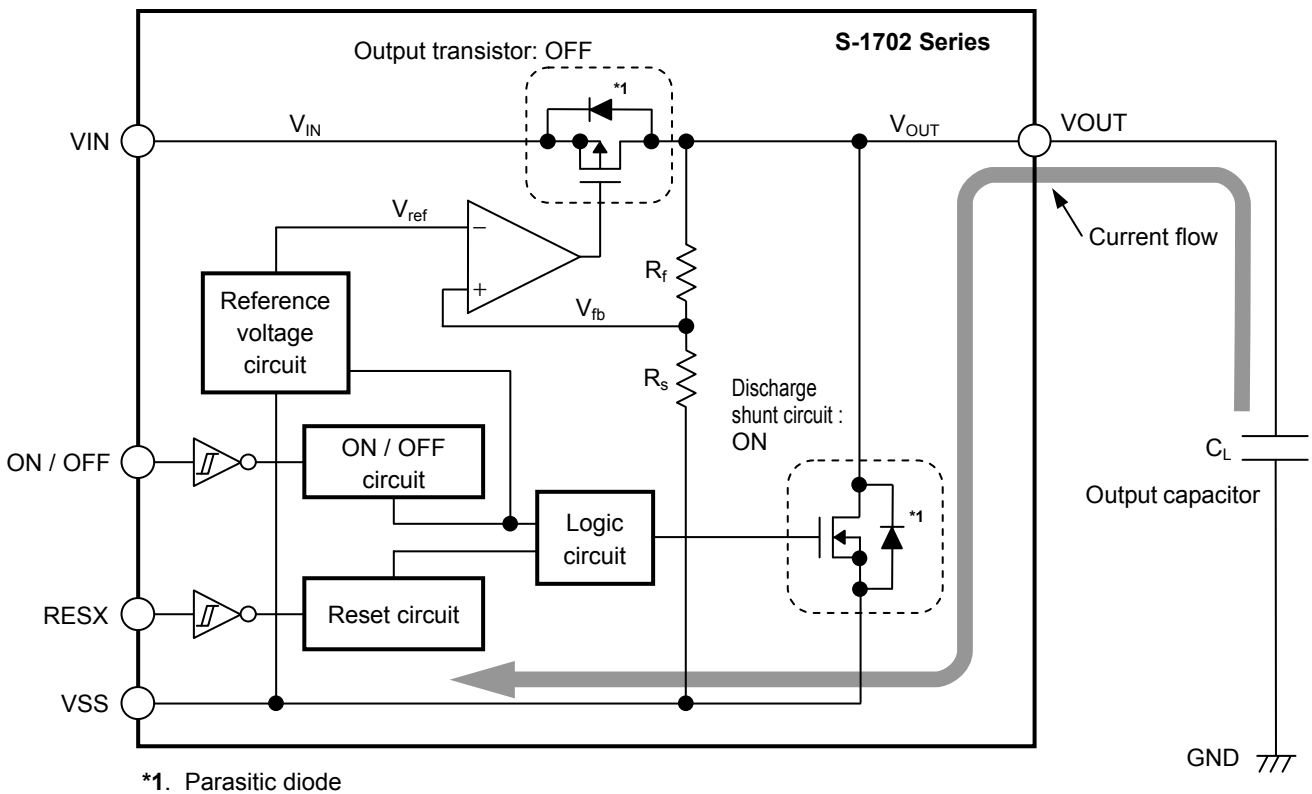
**Caution** Be sure that  $V_{OUT}$  does not exceed  $V_{IN} + 0.3\text{ V}$  to prevent the voltage regulator from being damaged due to inverse current flowing from the  $V_{OUT}$  pin through a parasitic diode to the  $V_{IN}$  pin, when the potential of  $V_{OUT}$  became higher than  $V_{IN}$ .

**2. 2. 2 Discharge shunt function**

The discharge shunt function is enabled in the S-1702Axx, Bxx, Cxx, Exx, Fxx, Gxx, Jxx, Lxx, and Nxx. When the regulator block is stopped, the output transistor is turned off and the discharge shunt circuit is turned on according to the combination of the ON / OFF and the RESX pins.

This operation causes the charge in the output capacitor ( $C_L$ ) to be discharged, and forcibly sets the  $V_{OUT}$  pin the  $V_{SS}$  level.

The  $V_{OUT}$  pin is set at the  $V_{SS}$  level in a shorter time than the S-1702Dxx, Hxx, Kxx, Mxx, and Pxx, because they disable the discharge shunt function.



**Figure 27 Discharge Shunt Function**

### 3. Detector block

#### 3.1 Basic operation

Figure 28 shows a block diagram of the detector block.

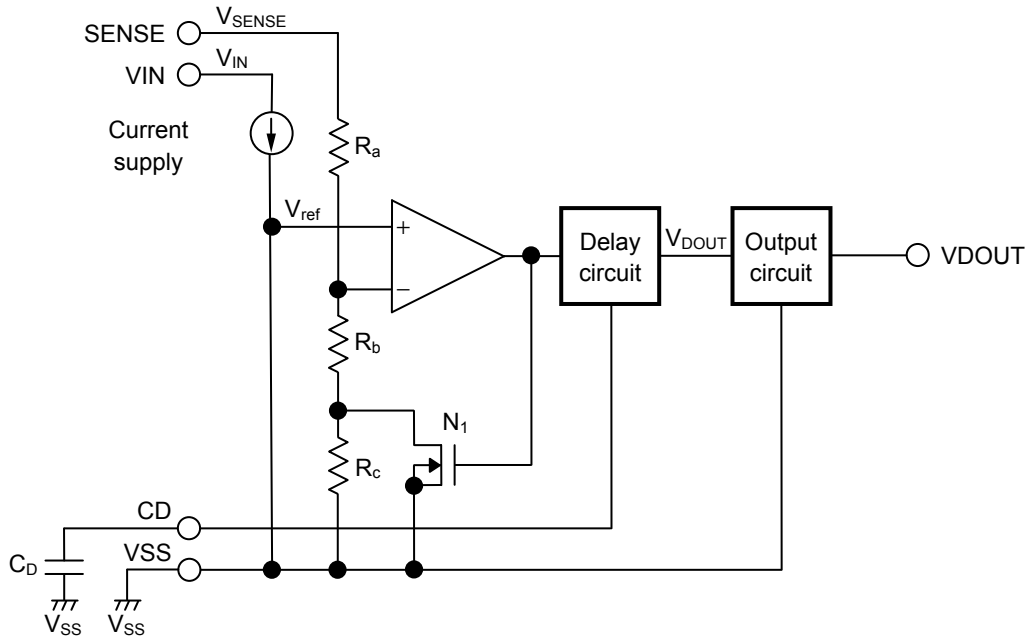


Figure 28

- (1) When the SENSE voltage ( $V_{SENSE}$ ) is the release voltage ( $+V_{DET}$ ) or more, the VDOUT pin outputs “H”. ((1) in **Figure 29**)

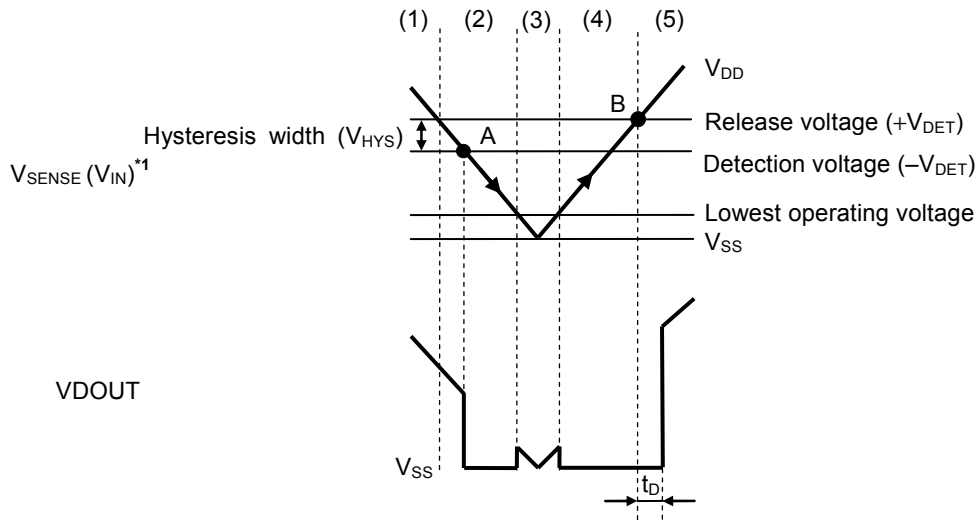
In this case, the transistor ( $N_1$ ) is off and the input voltage to the comparator is  $\frac{(R_b + R_c) \cdot V_{SENSE}}{R_a + R_b + R_c}$ .

- (2) Although the SENSE voltage ( $V_{SENSE}$ ) drops to the release voltage ( $+V_{DET}$ ) or less, the VDOUT pin outputs “H” when the SENSE voltage ( $V_{SENSE}$ ) is the detection voltage ( $-V_{DET}$ ) or more. If the SENSE voltage ( $V_{SENSE}$ ) is the detection voltage ( $-V_{DET}$ ) or less (refer to point **A** in **Figure 29**), the VDOUT pin outputs “L” ((2) in **Figure 29**).

The transistor ( $N_1$ ) is turned on and the input voltage to the comparator is  $\frac{R_b \cdot V_{SENSE}}{R_a + R_b}$ .

- (3) If the VIN input voltage ( $V_{IN}$ ) further drops to the lowest operating voltage of the S-1702 Series, the VDOUT pin is sets in high impedance. If the VDOUT pin is pulled up to the regulator output voltage ( $V_{OUT}$ ), the VDOUT pin outputs  $V_{OUT}$  (“H”) ((3) in **Figure 29**).
- (4) If the VIN input voltage ( $V_{IN}$ ) rises to the lowest operating voltage or more, the VDOUT pin outputs “L”. Although the SENSE voltage ( $V_{SENSE}$ ) exceeds the detection voltage ( $-V_{DET}$ ), it is the release voltage ( $+V_{DET}$ ) or less, the VDOUT pin outputs “L” ((4) in **Figure 29**).
- (5) If the SENSE voltage ( $V_{SENSE}$ ) rises to the release voltage ( $+V_{DET}$ ) or more (see point **B** in **Figure 29**), the VDOUT pin outputs “H”. The VDOUT pin outputs “H” after it is delayed for  $t_D$  by the delay circuit ((5) in **Figure 29**).

In the S-1702 Series, the detection voltage ( $V_{DOUT}$ ) can be set within the range of 1.3 V to 5.2 V (operating voltage range:  $V_{IN} = 0.8$  V to 6.5 V).

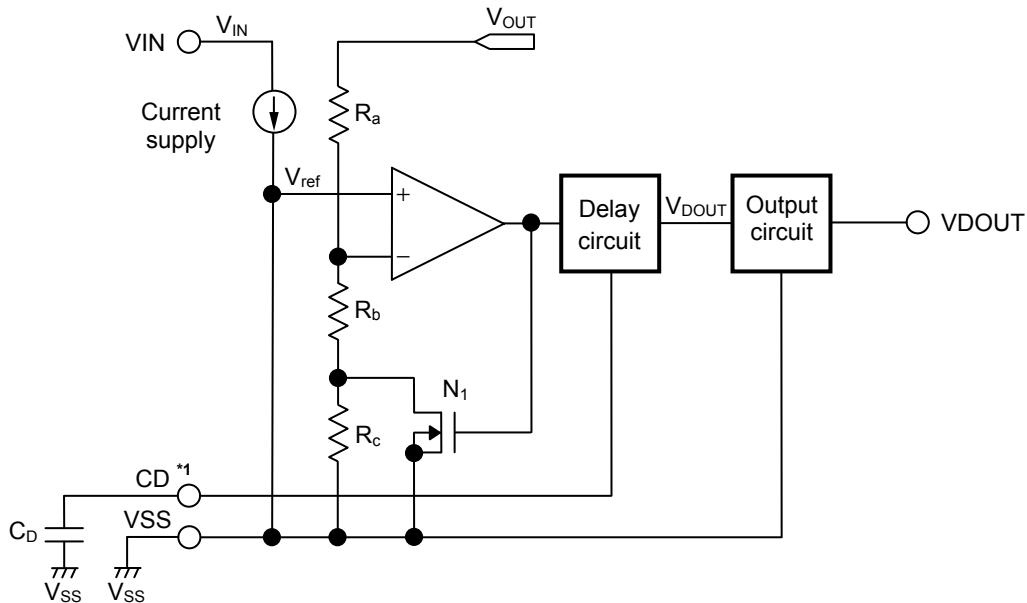


\*1. When the SENSE pin is connected to the VIN pin.

Figure 29 Operation

3. 1. 1 Regulator output voltage ( $V_{OUT}$ ) detection types (S-1702Axx, Bxx, Cxx, Dxx, Lxx, Mxx)

Each detector block of S-1702Axx, Bxx, Cxx, Dxx, Lxx, and Mxx detects the regulator output voltage ( $V_{OUT}$ ).



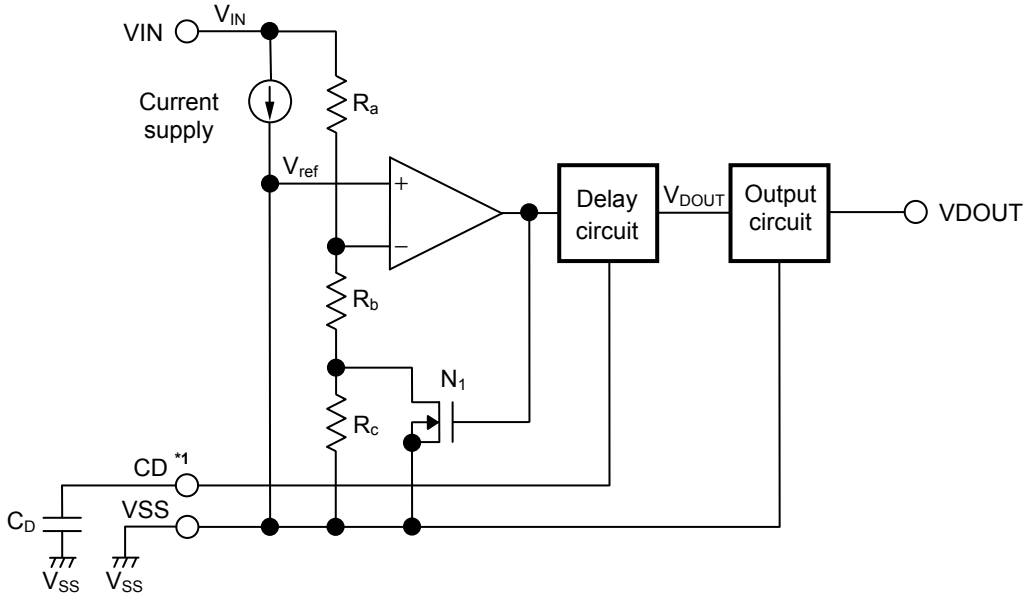
\*1. S-1702Lxx and S-1702Mxx only

Figure 30 Block Diagram (Regulator Output Voltage ( $V_{OUT}$ ) Detection Type)

**Caution** If the input voltage or load current changes transiently, undershoot or overshoot occurs in the regulator output voltage ( $V_{OUT}$ ). In the product types that the regulator output voltage is detected by the detector, if the output voltage reaches the detection voltage or less due to undershoot, the detector operates so that a reset signal may be output. To prevent this, set the value of the capacitor so that the value of undershoot is the minimum, or set the voltage range in which the difference of the output voltage and the detection voltage is undershoot or more.

**3. 1. 2 Input voltage ( $V_{IN}$ ) detection types (S-1702Exx, Fxx, Gxx, Hxx, Nxx, Pxx)**

Each detector block of S-1702Exx, Fxx, Gxx, Hxx, Nxx, and Pxx detects the input voltage ( $V_{IN}$ ).

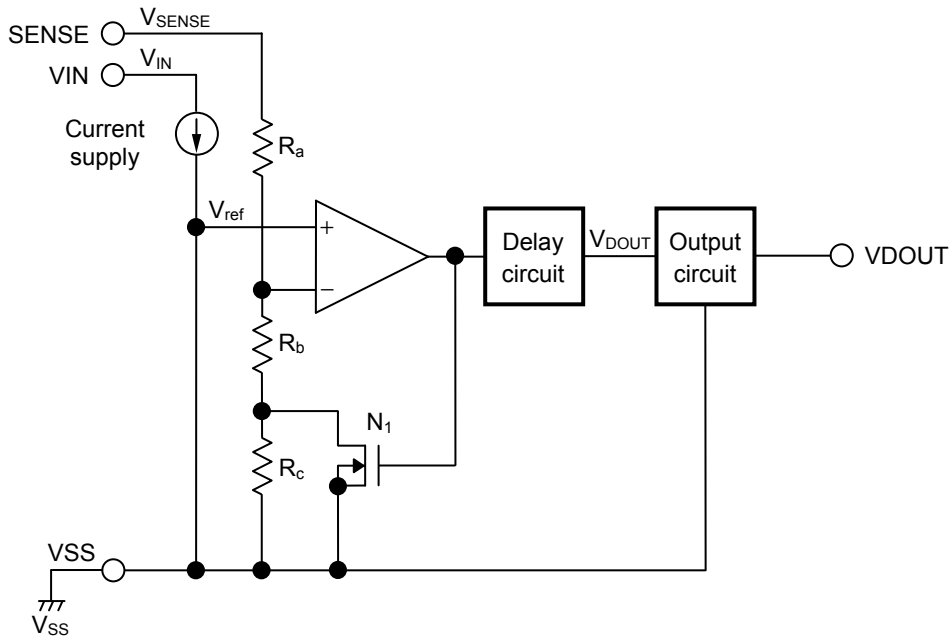


\*1. S-1702Nxx and S-1702Pxx only

**Figure 31 Block Diagram (Input Voltage ( $V_{IN}$ ) Detection Type)**

**3. 1. 3 SENSE voltage ( $V_{SENSE}$ ) detection types (S-1702Jxx, Kxx)**

Each detector block of S-1702Jxx and Kxx detects the SENSE voltage ( $V_{SENSE}$ ).



**Figure 32 Block Diagram (SENSE Voltage ( $V_{SENSE}$ ) Detection Type)**

**Caution** Use the SENSE pin as an input pin when detecting the external power supply voltage. If applying an input voltage ( $V_{IN}$ ) while a potential is being applied to the SENSE pin, an error occurs in the release voltage of the detector. Apply a voltage to the SENSE pin after applying the input voltage ( $V_{IN}$ ).

**3.2 Delay circuit**

**3.2.1 Internal delay types (S-1702Axx, Bxx, Cxx, Dxx, Exx, Fxx, Gxx, Hxx, Jxx, Kxx)**

In the internal delay types, when  $V_{SENSE}$  is turned on, the delay circuit makes a certain delay, after the point when  $V_{SENSE}$  has reached the release voltage ( $+V_{DET}$ ), and sets the  $V_{DOUT}$  pin to output an output signal (refer to point **B** in **Figure 29**). The delay circuit does not make delay when  $V_{SENSE}$  is the detection voltage ( $-V_{DET}$ ) or less (refer to point **A** in **Figure 29**).

The delay time ( $t_D$ ) is fixed in the internal circuit of internal delay types.

**3.2.2 External delay types (S-1702Lxx, Mxx, Nxx, Pxx)**

In the external delay types, the delay time of the detection signal can be set by connecting a capacitor ( $C_D$ ) between the  $CD$  and  $V_{SS}$  pins.

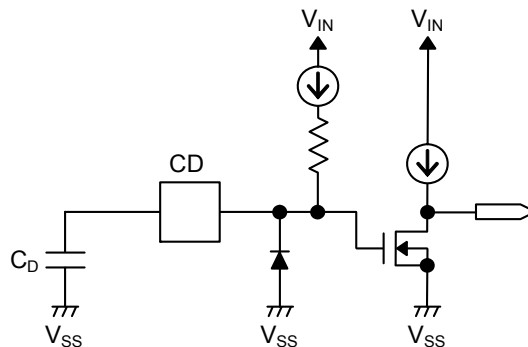
The delay time ( $t_D$ ) is determined according to the built-in constant current, approx. 100 nA (typ.), and the time constant of the external capacitor ( $C_D$ ), and can be calculated by the following equation.

$$t_D [\text{ms}] = \text{Delay constant} \times C_D [\text{nF}]$$

The delay constant ( $T_a = +25^\circ\text{C}$ ) is as follows.

Delay constant: 5.3 (min.), 6.3 (typ.), 7.3 (max.)

**Figure 33** shows the equivalent circuit of the  $CD$  pin (external delay type).

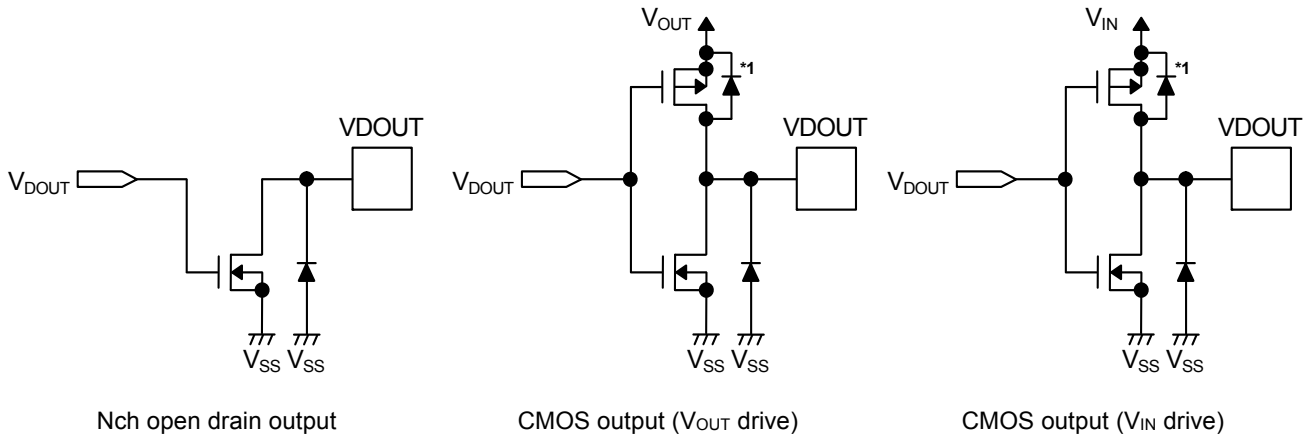


**Figure 33 Equivalent Circuit of CD Pin (External Delay Type)**

- Caution**
1. Design the board so that a current will not flow into or flow out from the  $CD$  (RESX) pin, because this pin's impedance is high. (Otherwise that may provide incorrect delay time.)
  2. There is no limit for the capacitance of the external capacitor ( $C_D$ ) as long as the leakage current of the capacitor can be ignored against the built-in constant current value. Leakage current causes deviation in delay time. When the leakage current is the built-in constant current or more, the IC does not release.

### 3.3 Output Circuit

Either Nch open drain output, CMOS output ( $V_{OUT}$  drive), or CMOS output ( $V_{IN}$  drive) is used for the VDOUT pin. For details, refer to “Table 2 Output Types of VDOUT Pin”. The equivalent circuits are shown below.



\*1. Parasitic diode

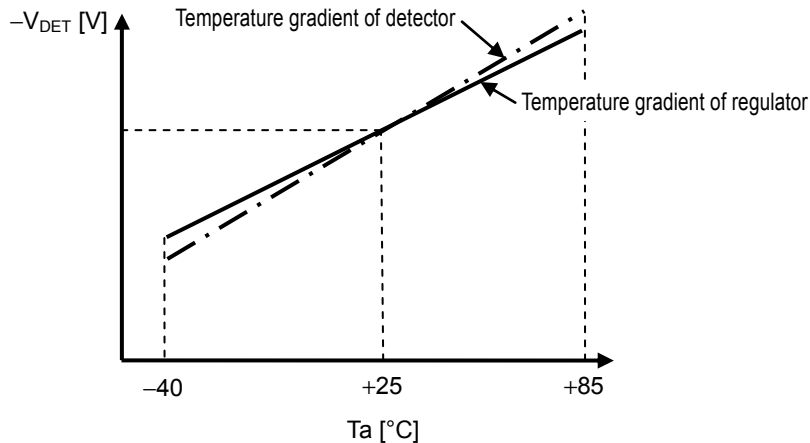
**Figure 34 Equivalent Circuits of VDOUT Pin**

**4. Relation of temperature coefficients of detector and regulator blocks**

The S-1702 Series has a detector and a regulator in it, and each reference voltage circuit has the same structure so that both temperature coefficients of detector detection voltage and regulator output interlock.

**4.1 Positive temperature coefficient of regulator output**

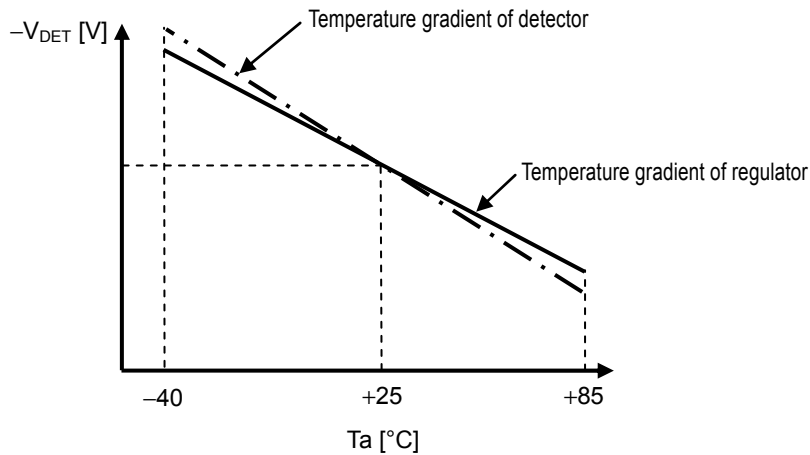
If the temperature coefficient of regulator output is positive, so is that of detector detection voltage (Figure 35).



**Figure 35 Relation of Temperature Coefficients of Detector and Regulator (When They Are Positive)**

**4.2 Negative temperature coefficient of regulator output**

If the temperature coefficient of regulator output is negative, so is that of detector detection voltage (Figure 36).



**Figure 36 Relation of Temperature Coefficients of Detector and Regulator (When They Are Negative)**

## ■ Precautions

- Wiring patterns for the VIN pin, VOUT pin and GND should be designed so that the impedance is low. When mounting an output capacitor between the VOUT pin and the VSS pin ( $C_L$ ) and a capacitor for stabilizing the input between the VIN pin and the VSS pin ( $C_{IN}$ ), the distance from the capacitors to these pins should be as short as possible.
- Note that generally the output voltage may increase when a series regulator is used at low load current (1.0 mA or less).
- Generally a series regulator may cause oscillation, depending on the selection of external parts. The following conditions are recommended for the S-1702 Series. However, be sure to perform sufficient evaluation under the actual usage conditions for selection, including evaluation of temperature characteristics.

Input capacitor ( $C_{IN}$ ):	1.0 $\mu$ F or more
Output capacitor ( $C_L$ ):	1.0 $\mu$ F or more
Equivalent series resistance (ESR):	10 $\Omega$ or less

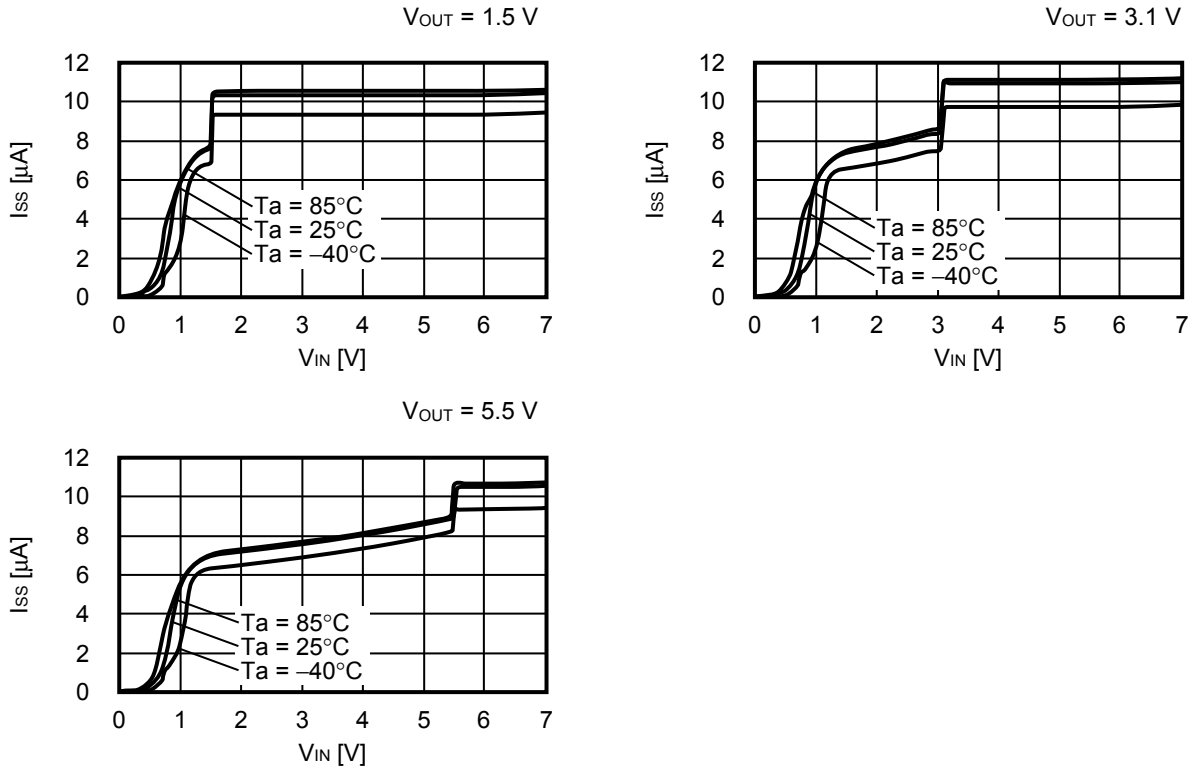
- The voltage regulator may oscillate when the impedance of the power supply is high and the input capacitance is small or an input capacitor is not connected.
- Overshoot may occur in the output voltage momentarily if the voltage is rapidly raised at power-on or when the power supply fluctuates. Sufficiently evaluate the output voltage at power-on with the actual device.
- The application conditions for the input voltage, the output voltage, and the load current should not exceed the package power dissipation.
- Do not apply an electrostatic discharge to this IC that exceeds the performance ratings of the built-in electrostatic protection circuit.
- In determining the output current, attention should be paid to the output current value specified in **Table 7** in “■ **Electrical Characteristics**” and footnote \*8 of the table.
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■ Characteristics (Typical Data)

1. Entire circuit

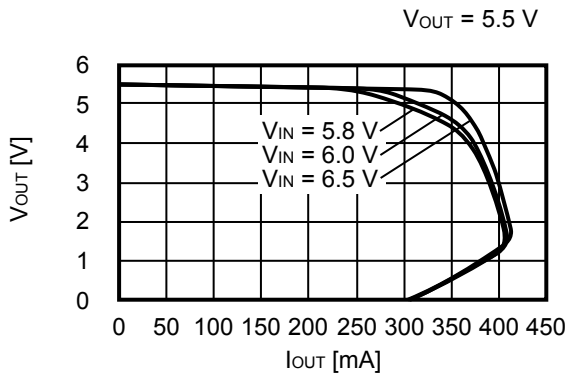
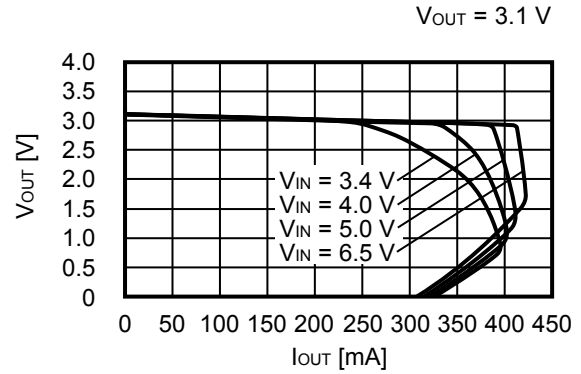
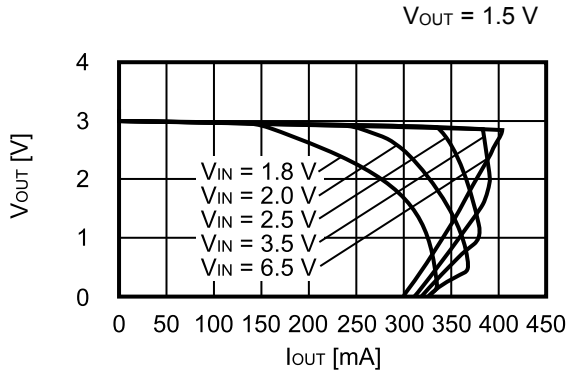
Current consumption during operation\*1 vs. Input voltage (Ta = +25°C)



\*1. Excluding current flowing in pull-up and pull-down resistors connected to the ON / OFF or RESX pins

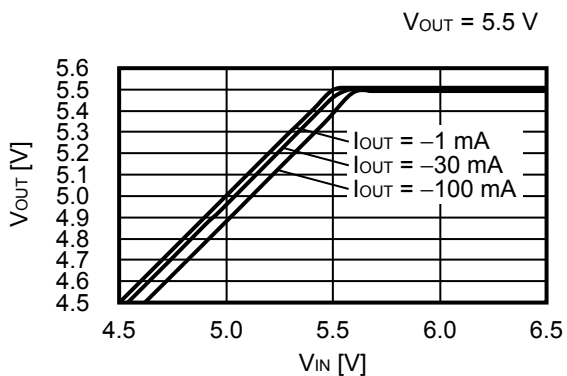
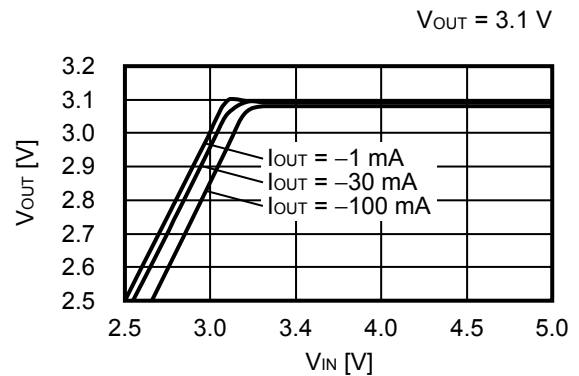
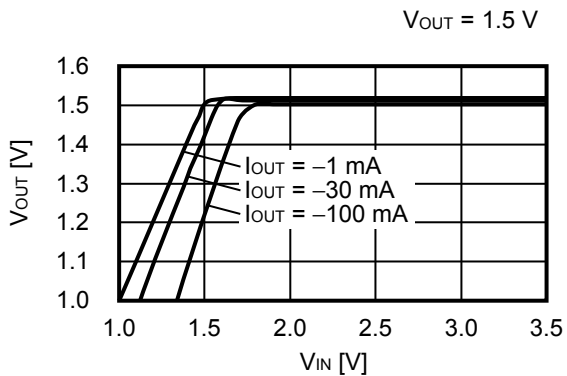
**2. Regulator block**

**2.1 Output voltage vs. Output current (when load current increases) (Ta = +25°C)**

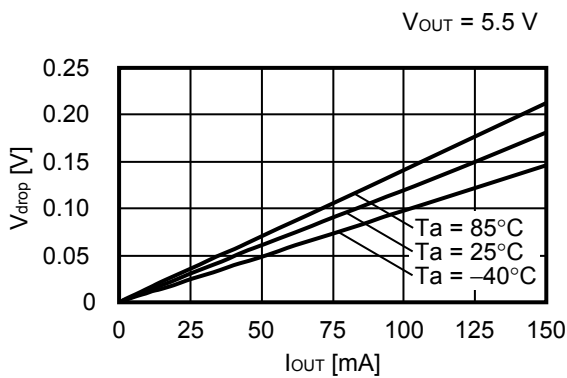
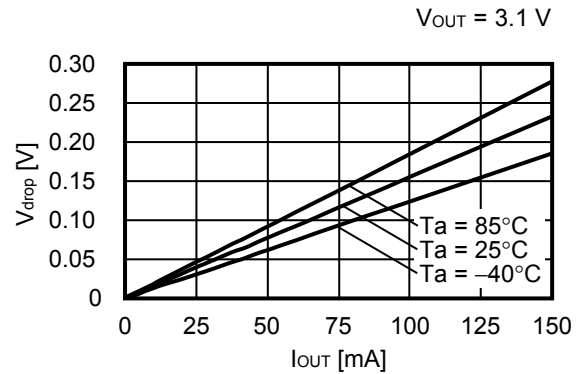
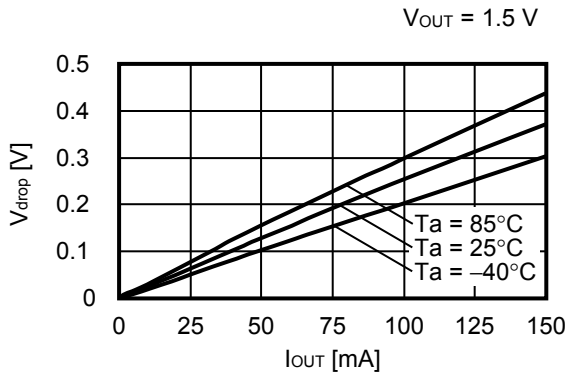


**Remark** In determining the output current, attention should be paid to the followings.  
 (1) The minimum output current value and footnote \*8 in **Table 7** in “**Electrical Characteristics**”.  
 (2) Power dissipation of package

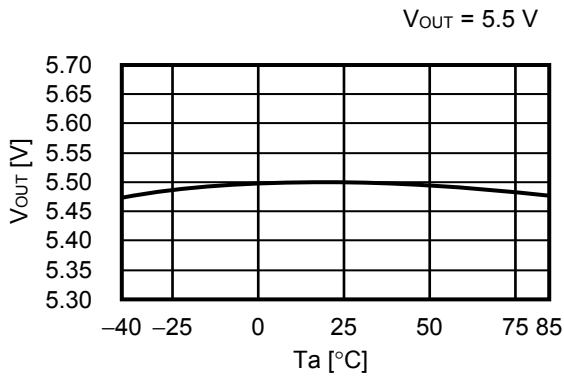
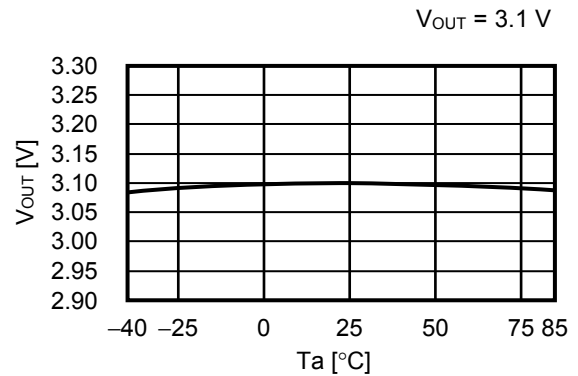
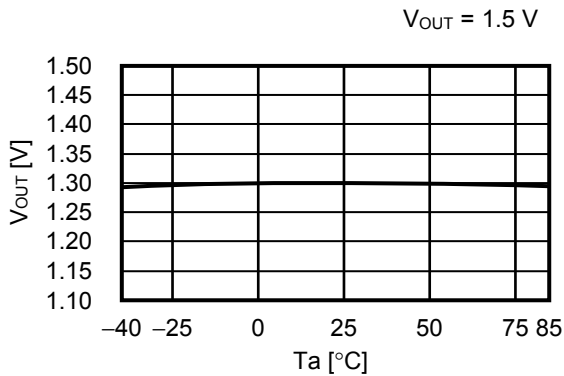
**2.2 Output voltage vs. Input voltage (Ta = +25°C)**



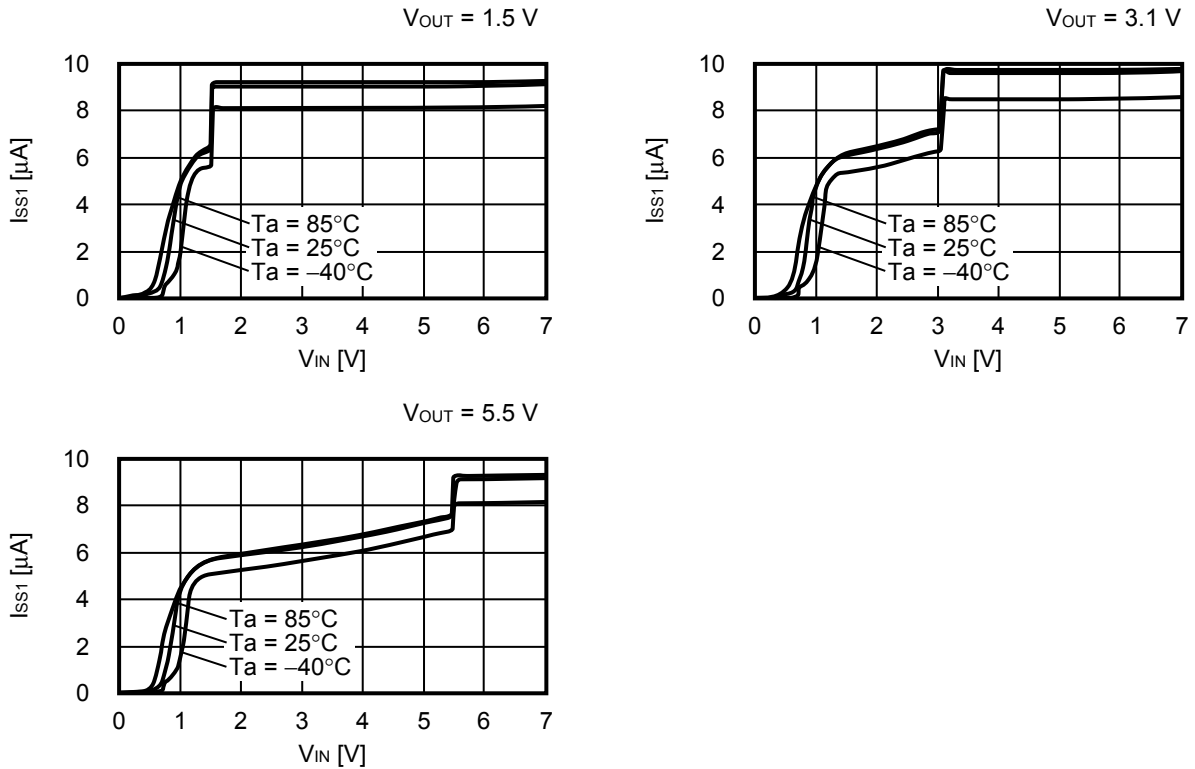
**2.3 Dropout voltage vs. Output current**



**2.4 Output voltage vs. Ambient temperature**

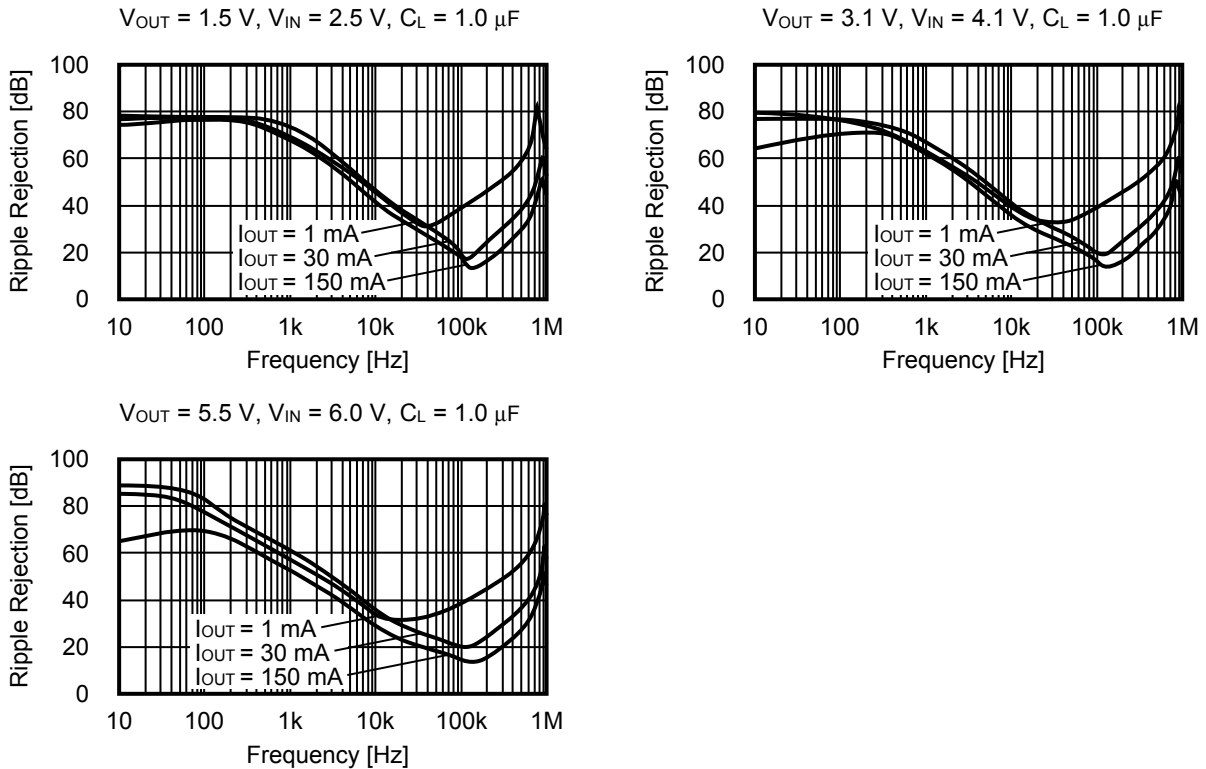


**2.5 Current consumption during operation at regulator block\*1 vs. Input voltage**



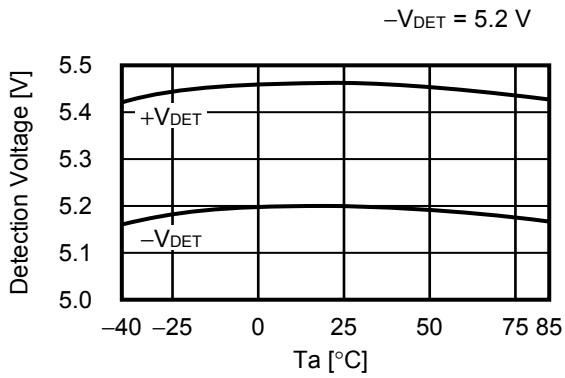
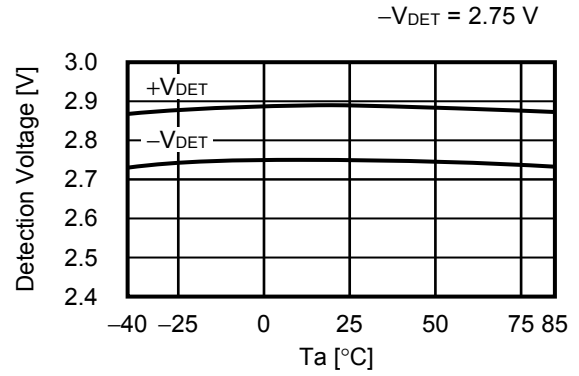
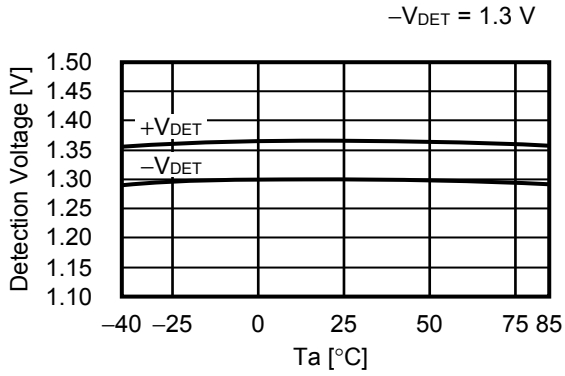
\*1. Excluding current flowing in pull-up and pull-down resistors connected to the ON / OFF or RESX pins

**2.6 Ripple rejection ratio ( $T_a = +25^\circ\text{C}$ )**

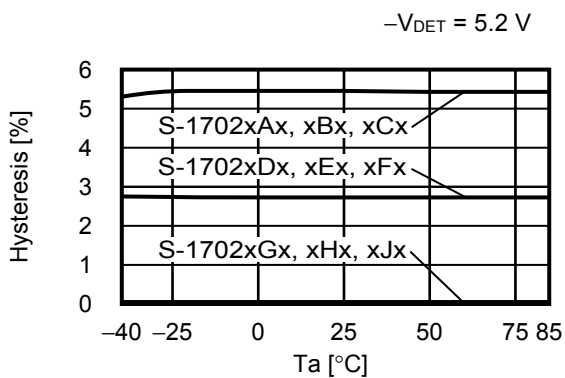
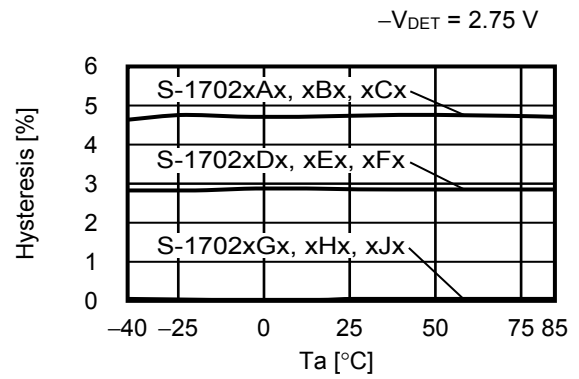
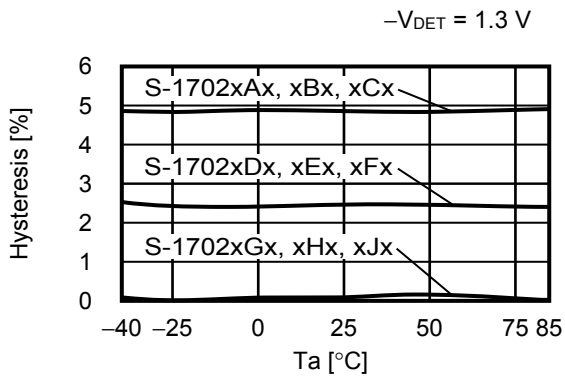


### 3. Detector block

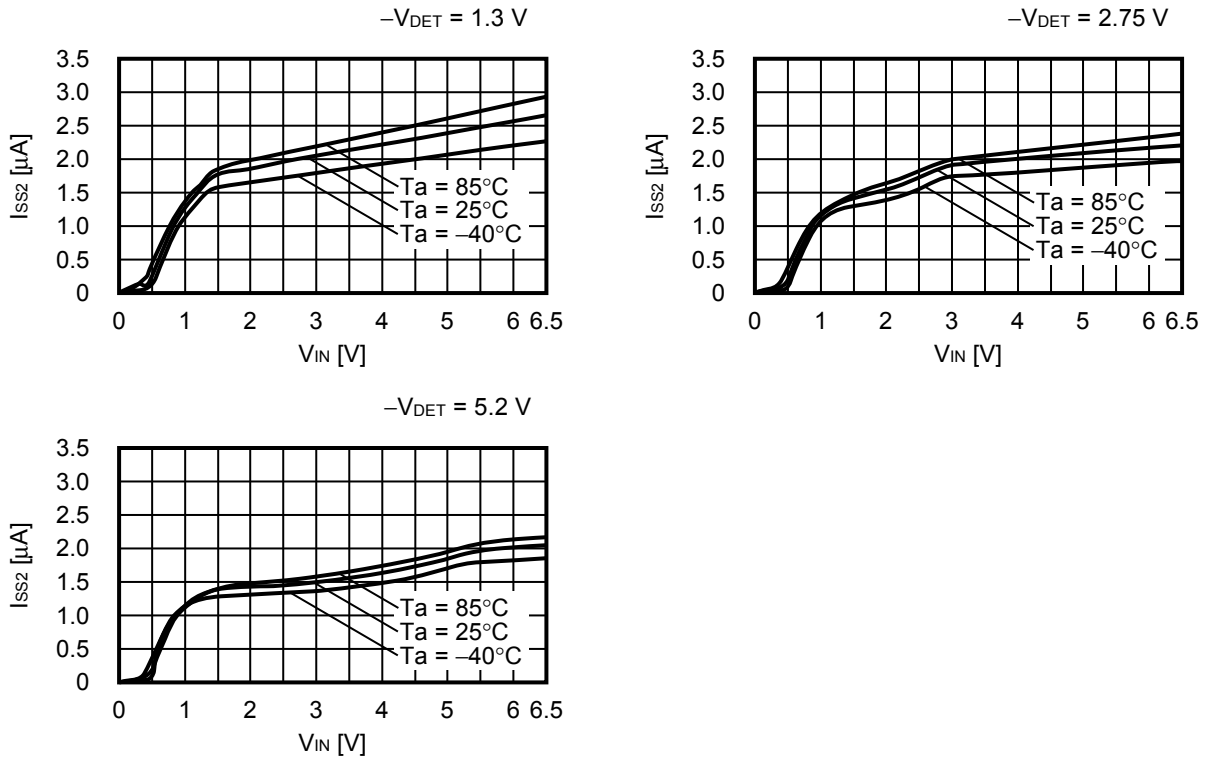
#### 3.1 Detection voltage vs. Ambient temperature



#### 3.2 Hysteresis width vs. Ambient temperature

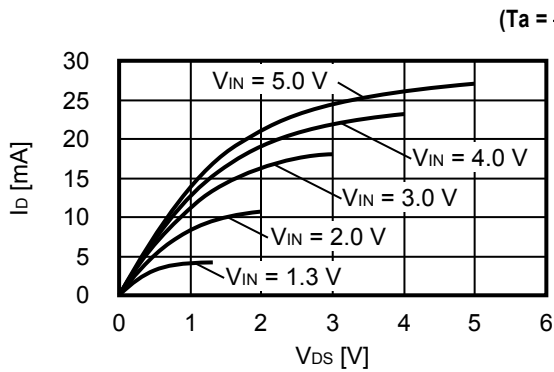


**3.3 Current consumption during operation at detector block\*1 vs. Input voltage**

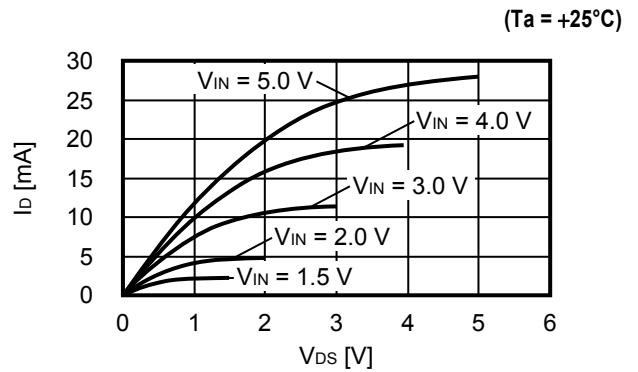


\*1. Excluding current flowing in pull-up and pull-down resistors connected to the ON / OFF or RESX pins

**3.4 Detector output voltage vs. Nch transistor characteristics ( $I_D$  vs.  $V_{DS}$  characteristics)**

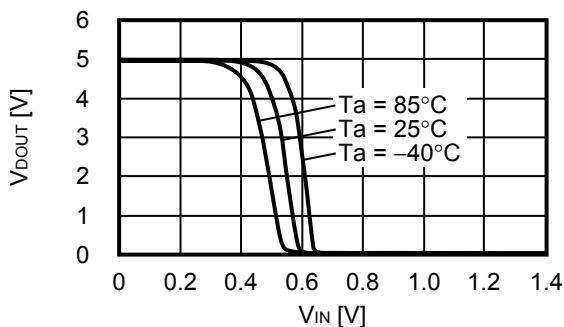


**3.5 Detector output voltage vs. Pch transistor characteristics ( $I_D$  vs.  $V_{DS}$  characteristics)**

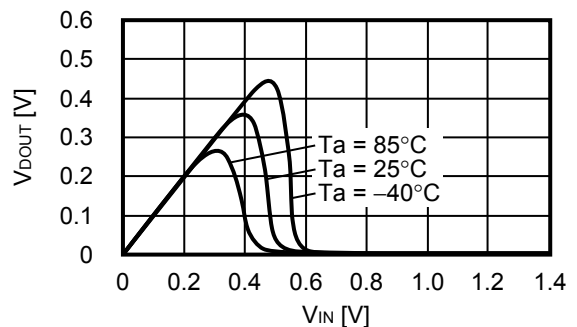


**3.6 Detector output voltage vs. Input voltage**

CMOS output



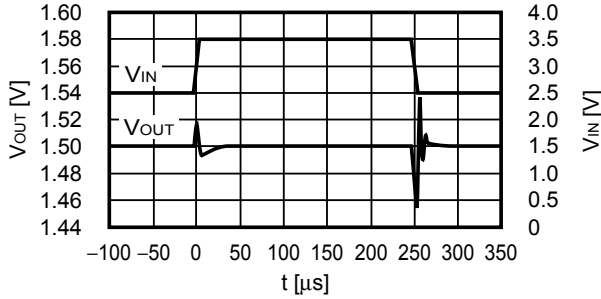
Nch open drain output



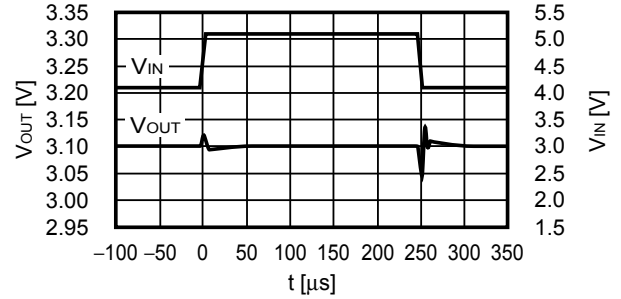
■ Reference Data

1. Input transient response characteristics (Ta = +25°C)

$I_{OUT} = 30 \text{ mA}$ ,  $t_r = t_f = 5.0 \mu\text{s}$ ,  $C_L = 1.0 \mu\text{F}$ ,  $C_{IN} = 1.0 \mu\text{F}$   
 $V_{OUT} = 1.5 \text{ V}$ ,  $V_{IN} = 2.5 \text{ V} \leftrightarrow 3.5 \text{ V}$

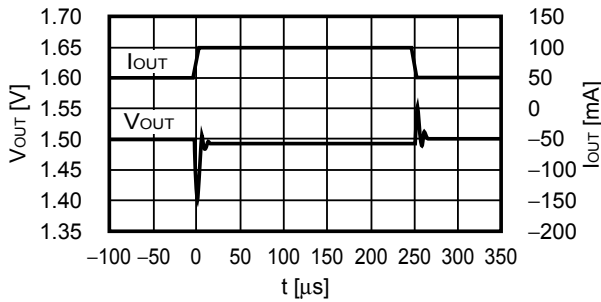


$I_{OUT} = 30 \text{ mA}$ ,  $t_r = t_f = 5.0 \mu\text{s}$ ,  $C_L = 1.0 \mu\text{F}$ ,  $C_{IN} = 1.0 \mu\text{F}$   
 $V_{OUT} = 3.1 \text{ V}$ ,  $V_{IN} = 4.1 \text{ V} \leftrightarrow 5.1 \text{ V}$

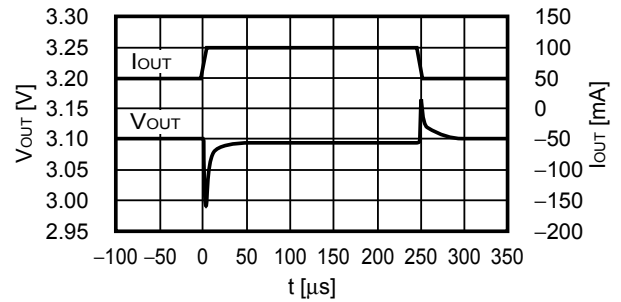


2. Load transient response characteristics (Ta = +25°C)

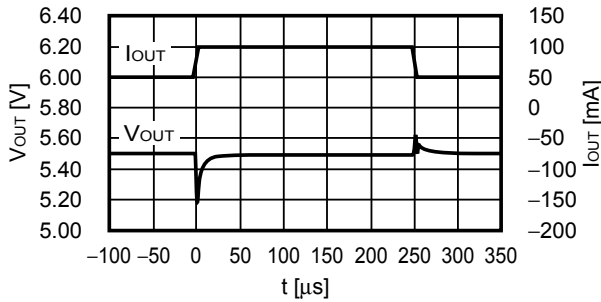
$V_{IN} = 2.5 \text{ V}$ ,  $C_L = 1.0 \mu\text{F}$ ,  $C_{IN} = 1.0 \mu\text{F}$   
 $V_{OUT} = 1.5 \text{ V}$ ,  $I_{OUT} = 50 \text{ mA} \leftrightarrow 100 \text{ mA}$



$V_{IN} = 4.0 \text{ V}$ ,  $C_L = 1.0 \mu\text{F}$ ,  $C_{IN} = 1.0 \mu\text{F}$   
 $V_{OUT} = 3.1 \text{ V}$ ,  $I_{OUT} = 50 \text{ mA} \leftrightarrow 100 \text{ mA}$

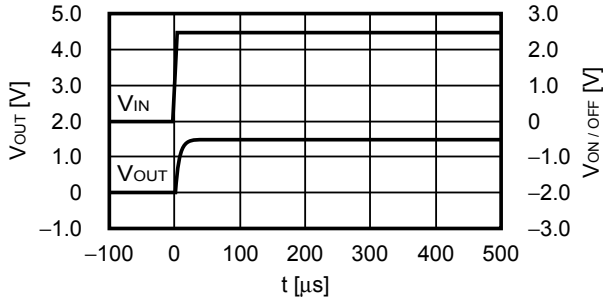


$V_{IN} = 6.0 \text{ V}$ ,  $C_L = 1.0 \mu\text{F}$ ,  $C_{IN} = 1.0 \mu\text{F}$   
 $V_{OUT} = 5.5 \text{ V}$ ,  $I_{OUT} = 50 \text{ mA} \leftrightarrow 100 \text{ mA}$

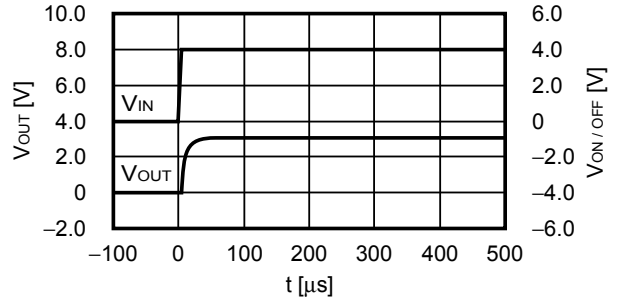


**3. ON/OFF pin transient response characteristics (Ta = +25°C)**

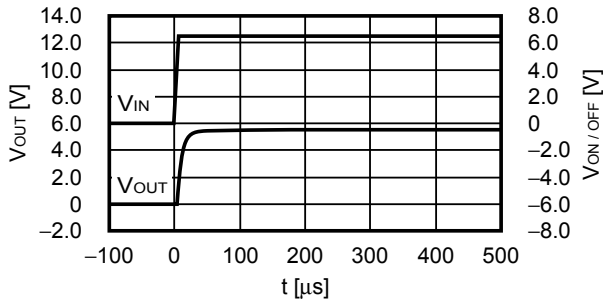
$V_{IN} = 2.5\text{ V}$ ,  $C_L = 1.0\ \mu\text{F}$ ,  $C_{IN} = 1.0\ \mu\text{F}$ ,  $I_{OUT} = 100\text{ mA}$   
 $V_{OUT} = 1.5\text{ V}$ ,  $V_{ON/OFF} = 0\text{ V} \rightarrow 2.5\text{ V}$



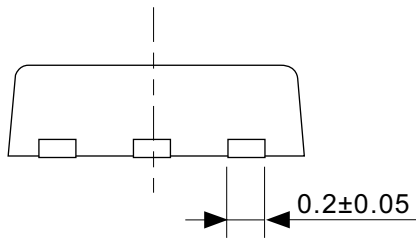
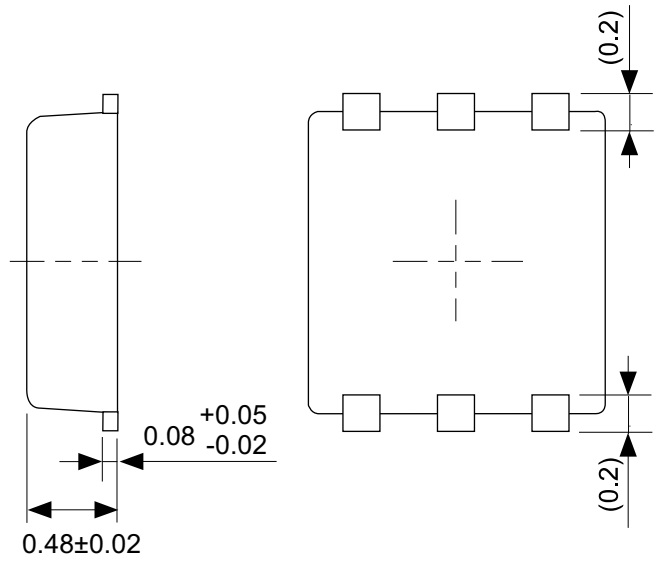
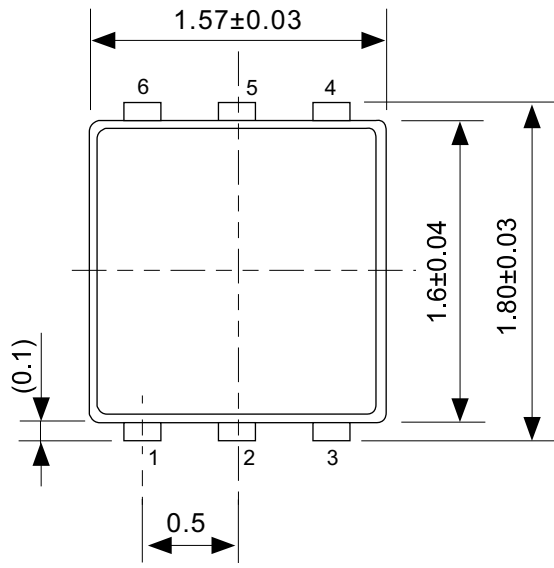
$V_{IN} = 4.0\text{ V}$ ,  $C_L = 1.0\ \mu\text{F}$ ,  $C_{IN} = 1.0\ \mu\text{F}$ ,  $I_{OUT} = 100\text{ mA}$   
 $V_{OUT} = 3.1\text{ V}$ ,  $V_{ON/OFF} = 0\text{ V} \rightarrow 4.0\text{ V}$



$V_{IN} = 6.0\text{ V}$ ,  $C_L = 1.0\ \mu\text{F}$ ,  $C_{IN} = 1.0\ \mu\text{F}$ ,  $I_{OUT} = 100\text{ mA}$   
 $V_{OUT} = 5.5\text{ V}$ ,  $V_{ON/OFF} = 0\text{ V} \rightarrow 6.5\text{ V}$

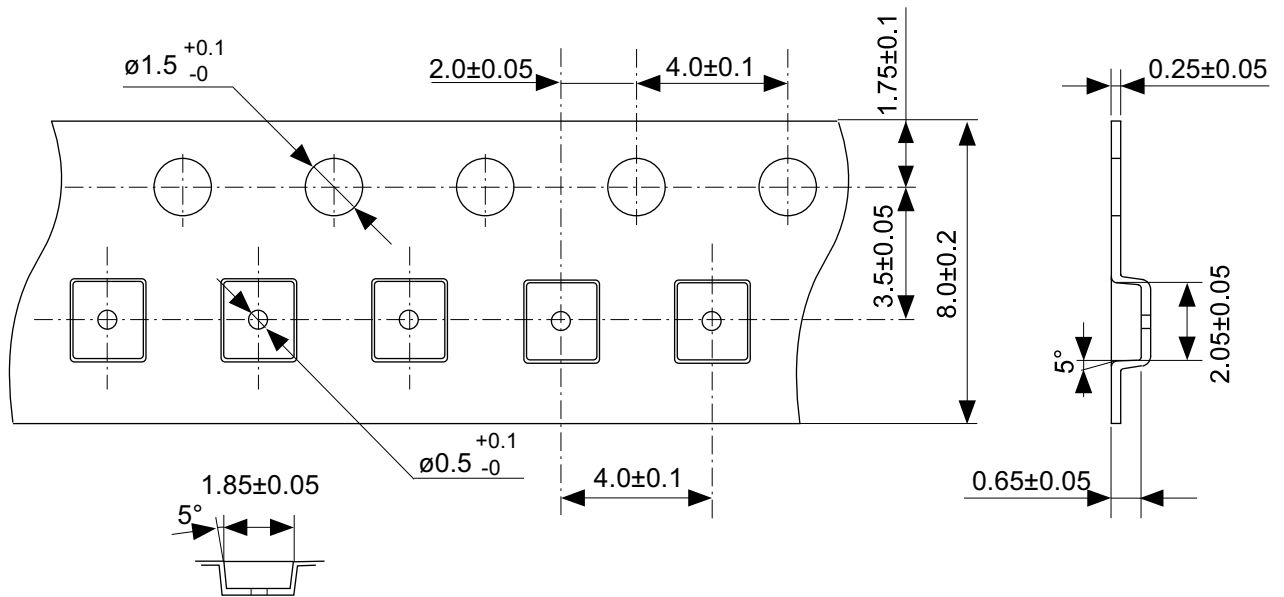






No. PG006-A-P-SD-2.0

TITLE	SNT-6A-A-PKG Dimensions
No.	PG006-A-P-SD-2.0
SCALE	
UNIT	mm
SII Semiconductor Corporation	



Feed direction

No. PG006-A-C-SD-1.0

TITLE	SNT-6A-A-Carrier Tape
No.	PG006-A-C-SD-1.0
SCALE	
UNIT	mm
SII Semiconductor Corporation	



Enlarged drawing in the central part



No. PG006-A-R-SD-1.0

TITLE	SNT-6A-A-Reel		
No.	PG006-A-R-SD-1.0		
SCALE		QTY.	5,000
UNIT			
SII Semiconductor Corporation			



※1. ランドパターンの幅に注意してください (0.25 mm min. / 0.30 mm typ.).  
 ※2. パッケージ中央にランドパターンを広げないでください (1.30 mm ~ 1.40 mm)。

- 注意
1. パッケージのモールド樹脂下にシルク印刷やハンダ印刷などしないでください。
  2. パッケージ下の配線上のソルダーレジストなどの厚みをランドパターン表面から0.03 mm 以下にしてください。
  3. マスク開口サイズと開口位置はランドパターンと合わせてください。
  4. 詳細は "SNTパッケージ活用の手引き" を参照してください。

※1. Pay attention to the land pattern width (0.25 mm min. / 0.30 mm typ.).  
 ※2. Do not widen the land pattern to the center of the package ( 1.30 mm ~ 1.40 mm ).

- Caution**
1. Do not do silkscreen printing and solder printing under the mold resin of the package.
  2. The thickness of the solder resist on the wire pattern under the package should be 0.03 mm or less from the land pattern surface.
  3. Match the mask aperture size and aperture position with the land pattern.
  4. Refer to "SNT Package User's Guide" for details.

※1. 请注意焊盘模式的宽度 (0.25 mm min. / 0.30 mm typ.).  
 ※2. 请勿向封装中间扩展焊盘模式 (1.30 mm ~ 1.40 mm)。

- 注意
1. 请勿在树脂型封装的下面印刷丝网、焊锡。
  2. 在封装下、布线上的阻焊膜厚度 (从焊盘模式表面起) 请控制在 0.03 mm 以下。
  3. 钢网的开口尺寸和开口位置请与焊盘模式对齐。
  4. 详细内容请参阅 "SNT 封装的应用指南"。

No. PG006-A-L-SD-4.1

TITLE	SNT-6A-A -Land Recommendation
No.	PG006-A-L-SD-4.1
SCALE	
UNIT	mm
SII Semiconductor Corporation	

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The user of these products should therefore take responsibility to give thorough consideration to safety design including redundancy, fire spread prevention measures, and malfunction prevention to prevent accidents causing injury or death, fires and social damage, etc. that may ensue from the products' failure or malfunction.  
The entire system must be sufficiently evaluated and applied on customer's own responsibility.
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1.0-2016.01

